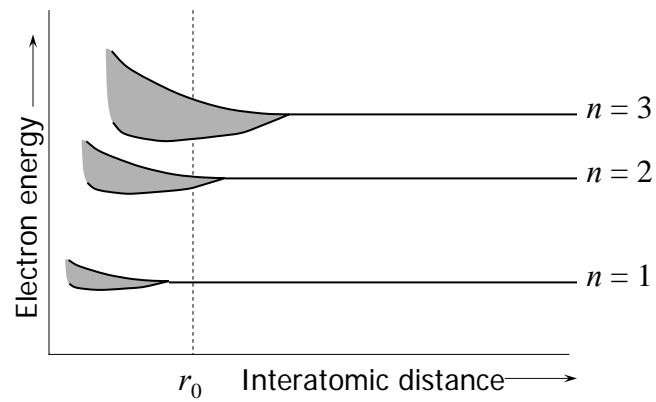
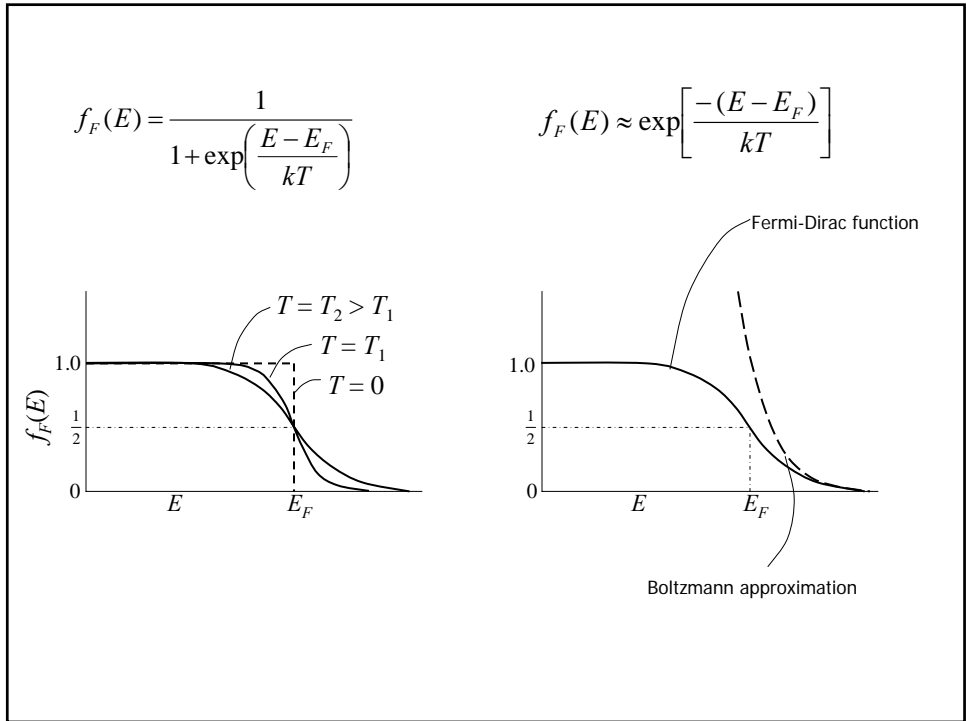
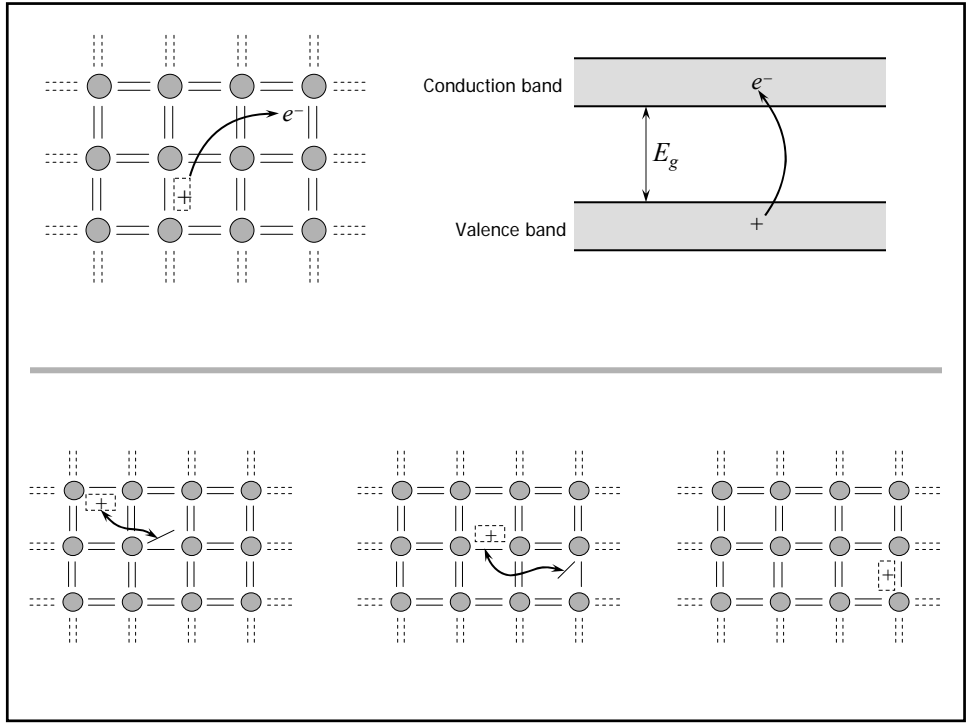
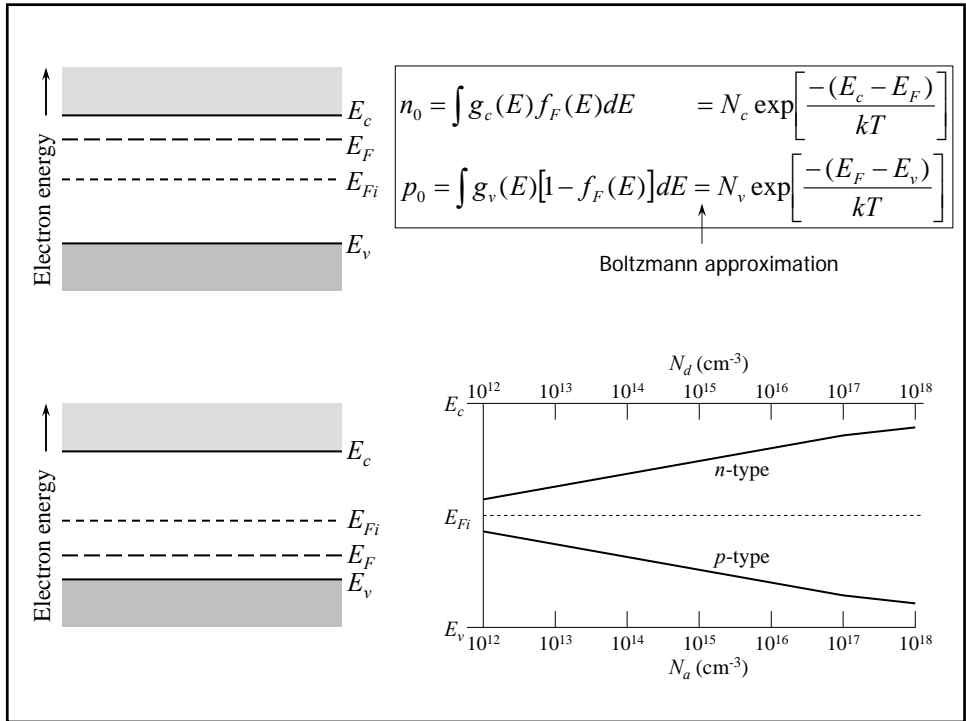
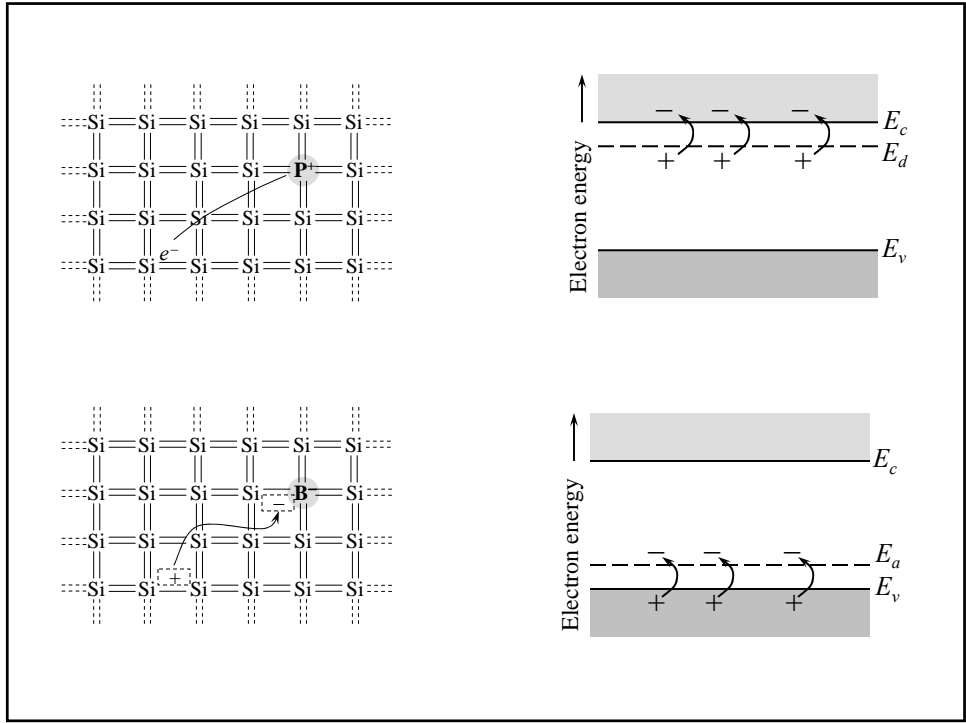


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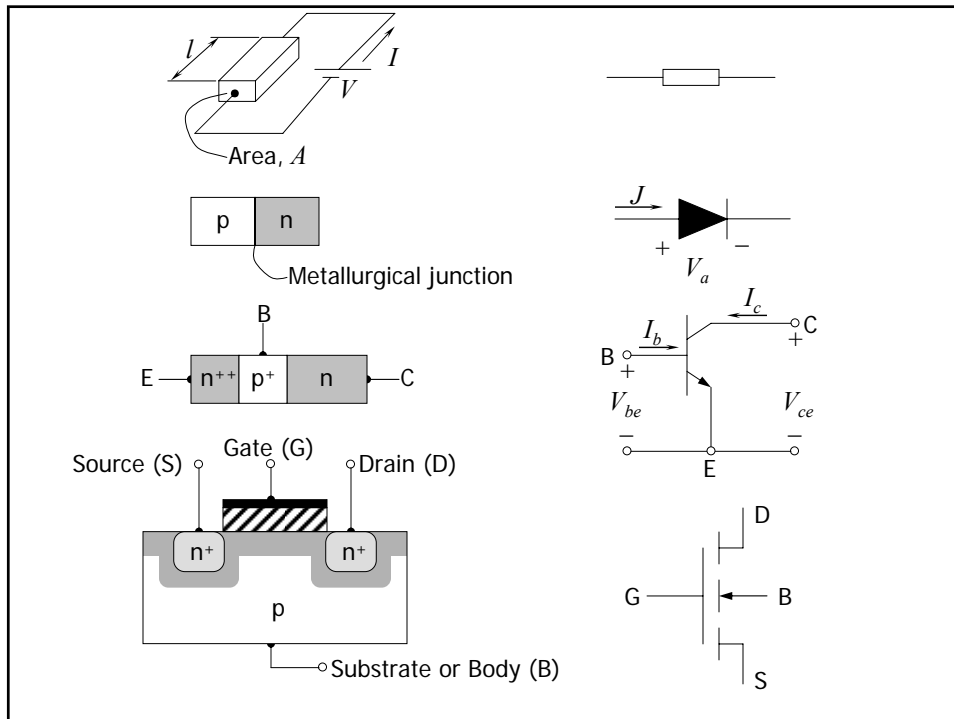
$$n_i^2 = N_C N_V \exp\left(-\frac{E_g}{kT}\right) \leftarrow \text{material characteristic}$$

$$n_i^2 = n_0 p_0 \leftarrow \text{Valid if material is in thermal equilibrium and if Boltzmann approximation is valid!}$$

Application: Consider silicon with $N_d = 10^{18} \text{ cm}^{-3}$. Determine the free charge carrier concentration in thermal equilibrium

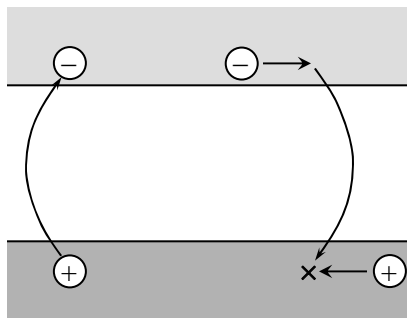
$$\left. \begin{array}{l} n_i = 1.5 \times 10^{10} \text{ cm}^{-3}; \quad n_i^2 = 2.25 \times 10^{20} \text{ cm}^{-6} \\ n_0 \approx N_d = 1.0 \times 10^{18} \text{ cm}^{-3} \end{array} \right\} \Rightarrow p_0 = \frac{n_i^2}{n_0} = 225 \text{ cm}^{-3}$$

Conclusion: In this n-type material the free-holes concentration, minority charge carriers, is orders of magnitude smaller than that of electrons, the majority charge carriers.



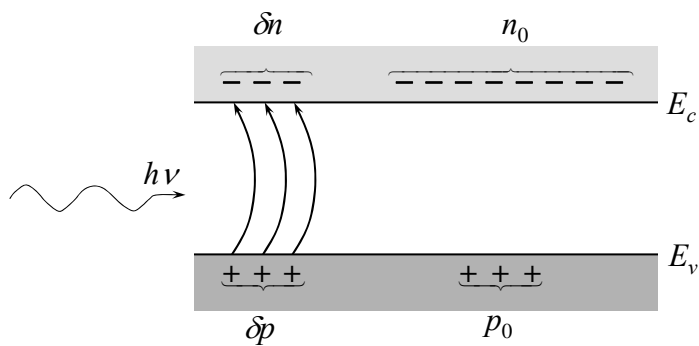
Generation/Recombination

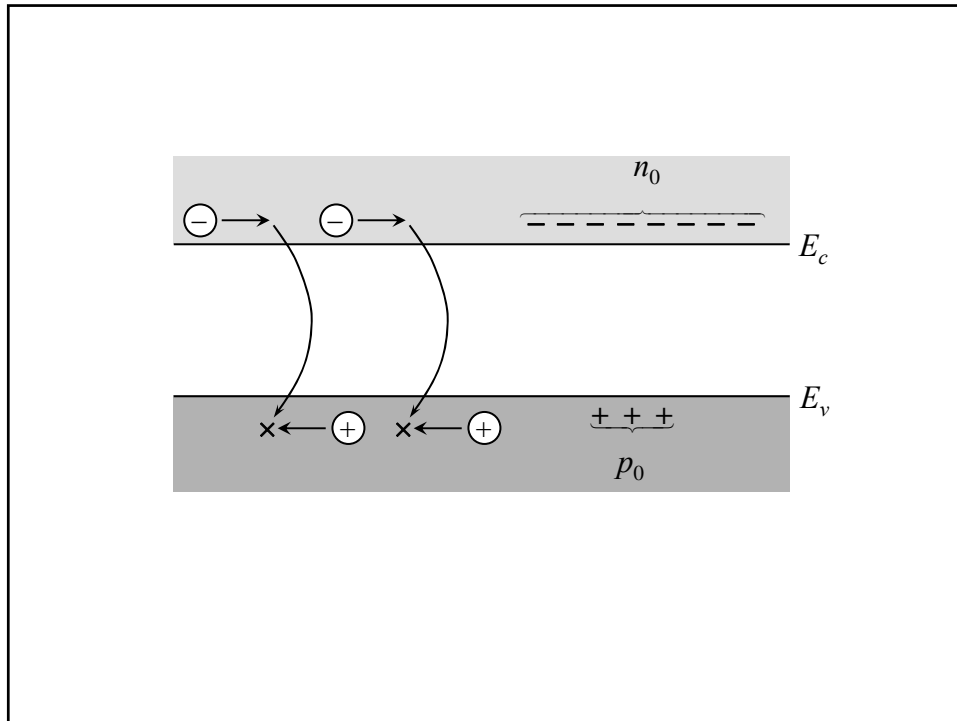
- In thermal equilibrium: thermal generation is equal to thermal recombination.
- In *static* equilibrium: *excess* generation equal to *excess* recombination.



Two generation-recombination processes

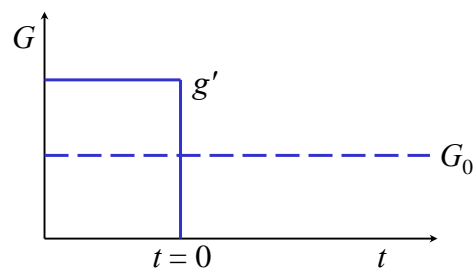
- Direct generation-recombination: generation and recombination of electron-hole pairs (thermal and as a result of other energy supply) across the forbidden energy band gap \Rightarrow “band-to-band recombination”.
- Generation and recombination via energy states in the forbidden energy band gap.





Study of recombination

Study recombination by investigating the effect of switching off a disturbance \Rightarrow find the relaxation time (life time) of the system to return to thermal equilibrium.



Determination of direct recombination

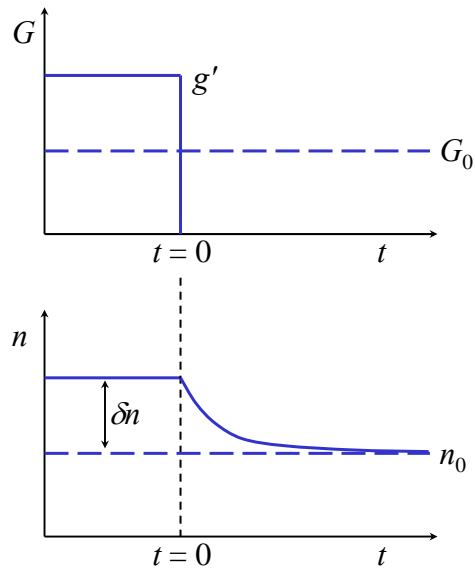
$$\frac{dn(t)}{dt} = g_{\text{thermal}} - \alpha_r n(t) p(t) = \alpha_r [n_i^2 - n(t) p(t)]$$

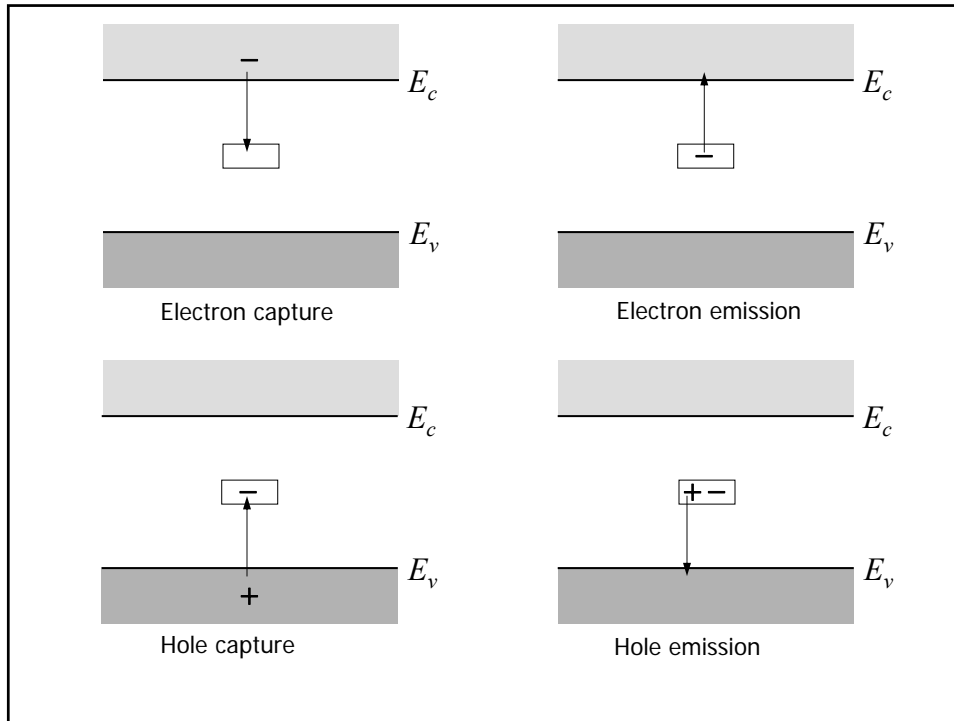
Low-level injection, p-type: $n_0 \ll \delta n \ll p_0$

$$\delta n(t) = \delta n(0) e^{-\alpha_r p_0 t} = \delta n(0) e^{-t/\tau_{n0}}$$

$$\tau_{n0} = \frac{1}{\alpha_r p_0}$$

$$R_n = R_p = \frac{\delta n(t)}{\tau_{n0}}$$





Recombination via states in the gap

$$R_n = R_p = \frac{C_n C_p N_t (np - n_i^2)}{C_n (n + n') + C_p (p + p')} \equiv R$$

$$n' = N_C \exp\left[\frac{-(E_C - E_t)}{kT}\right]$$

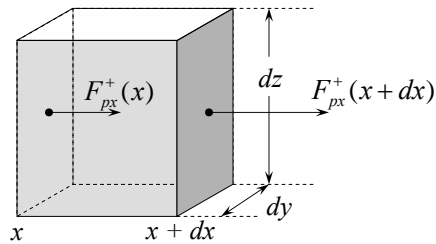
$$p' = N_V \exp\left[\frac{-(E_t - E_C)}{kT}\right]$$

Recombination via states in the gap

“Low-level” injection for n-type: $R = C_p N_t \delta p = \frac{\delta p}{\tau_{pt}}$

So:
$$\tau_{pt} = \frac{1}{C_p N_t}$$

Here, C_p is proportional to the capture cross section for holes and N_t is the density of states in the gap (trap density).



$$\frac{\partial p}{\partial t} dx dy dz = [F_{px}^+(x) - F_{px}^+(x + dx)] dy dz = -\frac{\partial F_{px}^+}{\partial x} dx dy dz$$

$$\boxed{\frac{\partial p}{\partial t} = -\frac{\partial F_p^+}{\partial x} + g_p - \frac{p}{\tau_{pt}}}$$

→ Defines also the lifetime of excess holes

Ambipolar transport equation

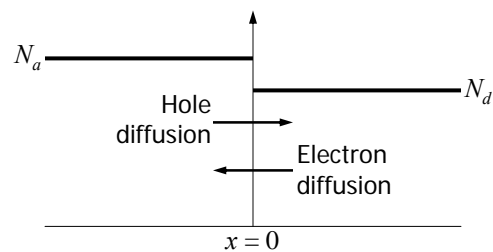
$$D_p \frac{\partial^2(\delta p)}{\partial x^2} - \mu_p E \frac{\partial(\delta p)}{\partial x} + g_p - \frac{p}{\tau_{pt}} = \frac{\partial(\delta p)}{\partial t}$$

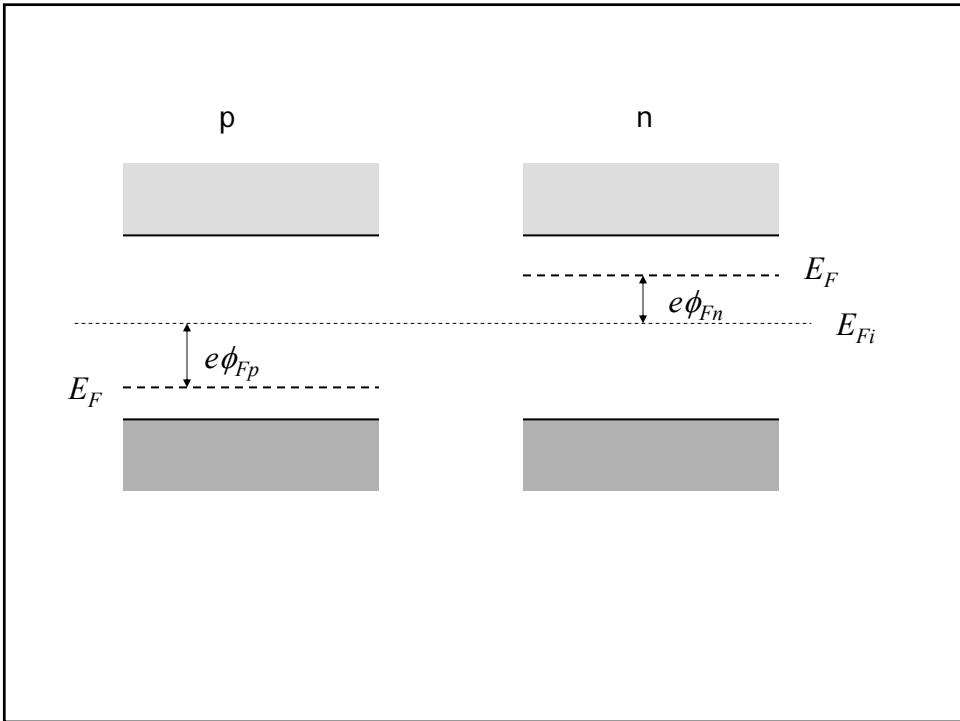
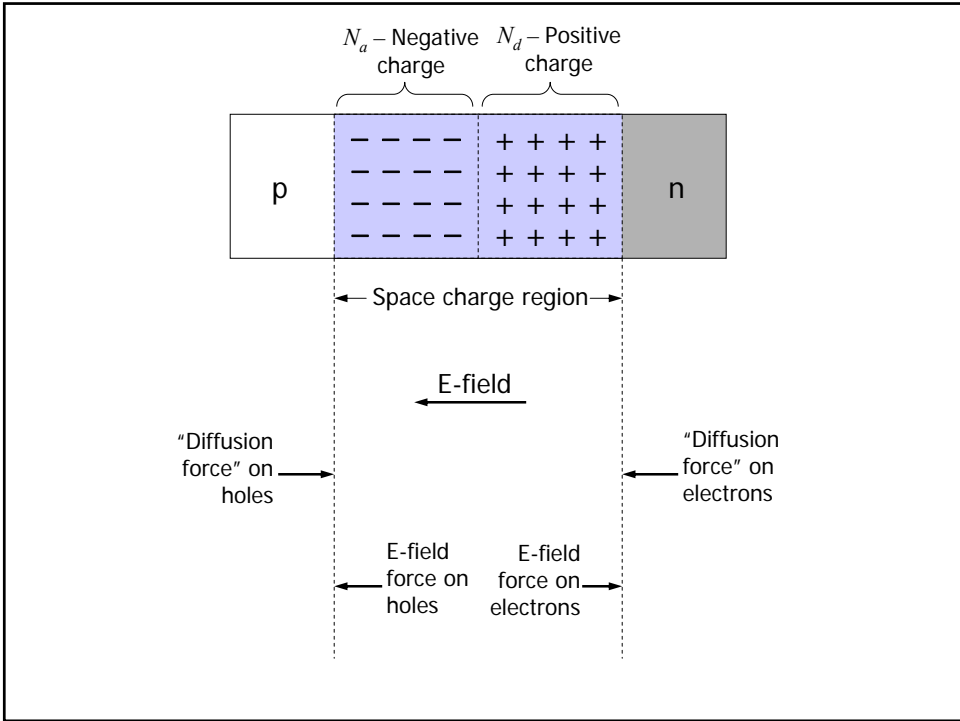
$$D_n \frac{\partial^2(\delta n)}{\partial x^2} + \mu_n E \frac{\partial(\delta n)}{\partial x} + g_n - \frac{n}{\tau_{nt}} = \frac{\partial(\delta n)}{\partial t}$$

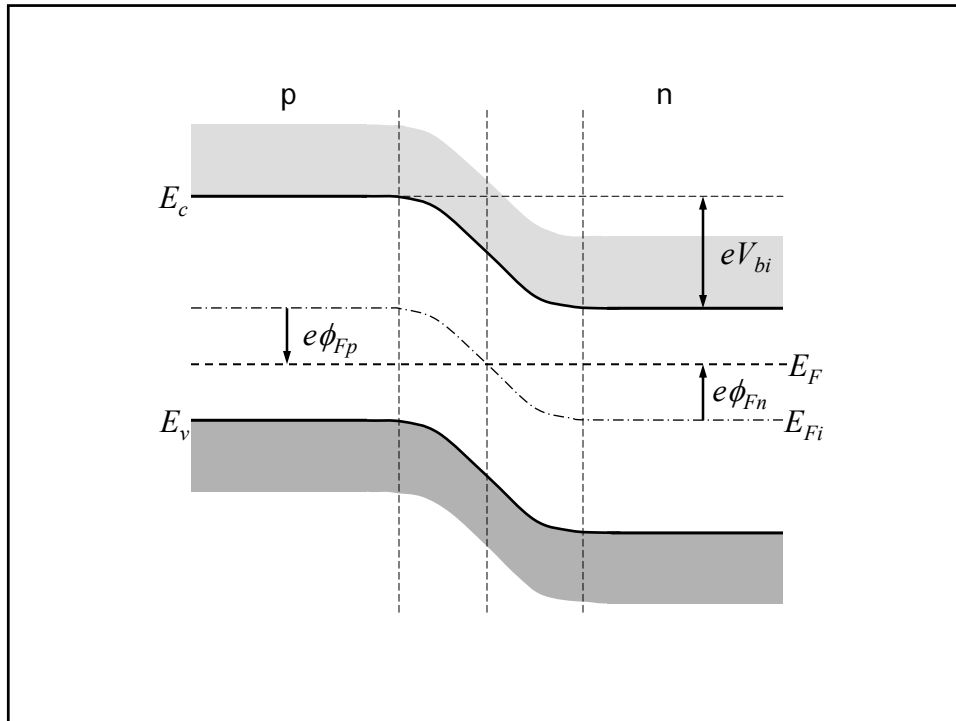
Important: the charge-carrier transport is determined by the minority charge carriers!!! Under the condition of low-level injection.



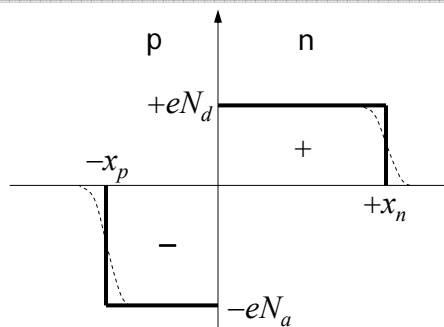
Metallurgical junction







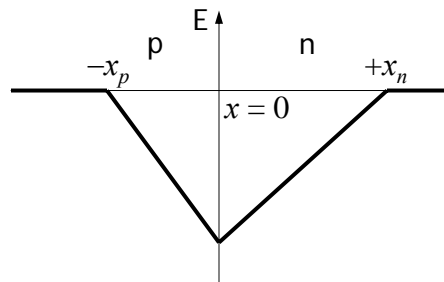
Abrupt depletion approximation



$$\frac{d^2\phi(x)}{dx^2} = -\frac{\rho(x)}{\epsilon_s} = -\frac{dE(x)}{dx}$$

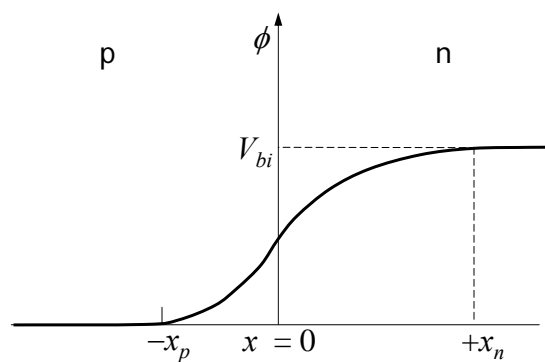
→ Poisson equation

Calculation electric field



$$E = \frac{-eN_a}{\epsilon_s}(x + x_p) \quad -x_p \leq x \leq 0$$

...and the potential



$$\phi(x) = \frac{eN_a}{2\epsilon_s}(x + x_p)^2 \quad (-x_p \leq x \leq 0)$$

Calculation V_{bi}

$$n\text{-side: } n_0 = n_i \exp[(E_F - E_{Fi})/kT] = n_i \exp[-e\phi_{Fn}/kT] \approx N_d$$

$$p\text{-side: } p_0 = n_i \exp[(E_{Fi} - E_F)/kT] = n_i \exp[-e\phi_{Fp}/kT] \approx N_a$$

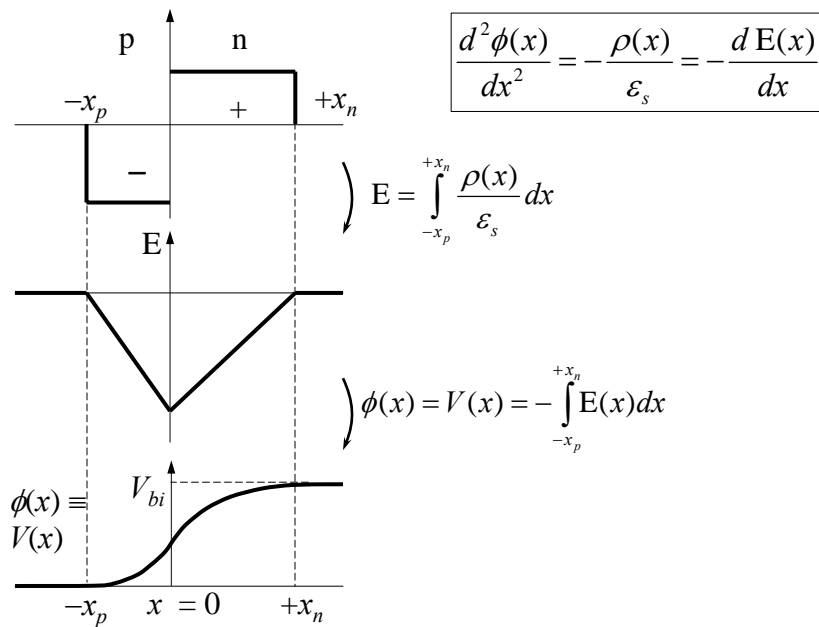
Then the potentials ϕ_{Fn} and ϕ_{Fp} become:
$$\phi_{Fn} = \frac{kT}{e} \ln\left(\frac{N_d}{n_i}\right)$$

$$\phi_{Fp} = \frac{kT}{e} \ln\left(\frac{N_a}{n_i}\right)$$

...and we find for the built-in potential difference:

$$V_{bi} = \phi_{Fn} + \phi_{Fp} = \frac{kT}{e} \ln\left(\frac{N_a N_d}{n_i^2}\right) = \frac{e}{2\epsilon_s} (N_d x_n^2 + N_a x_p^2)$$

Relation band diagram \Leftrightarrow electrostatic quantities



Calculation depletion width

Depletion width follow from charge neutrality: $N_a x_p = N_d x_n$

..... and from: $W = x_n + x_p$

Then we obtain:

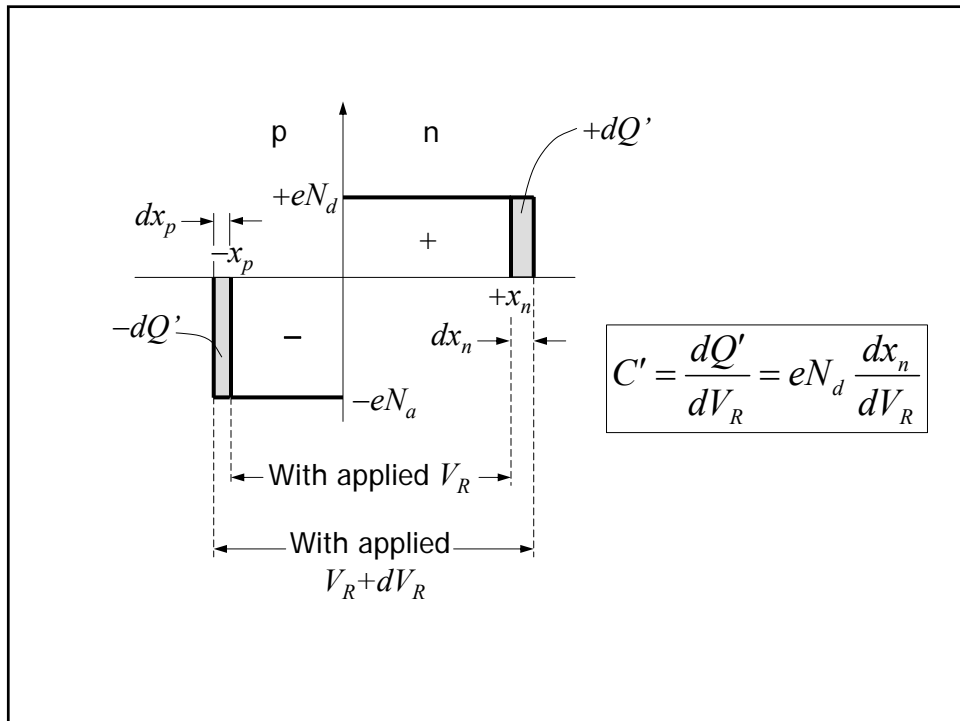
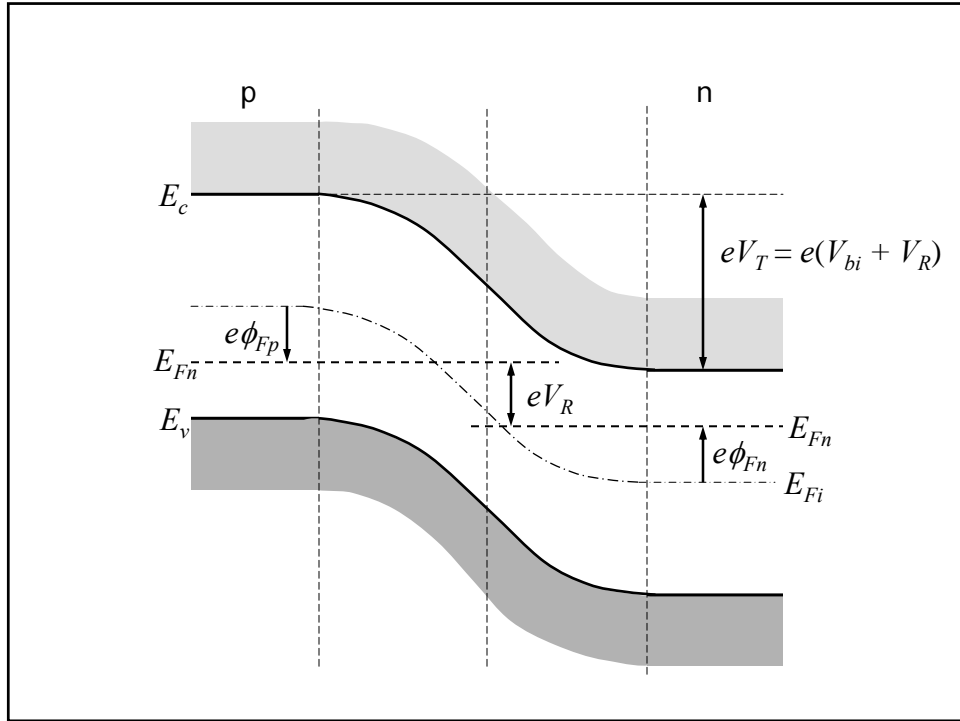
$$W = \left\{ \frac{2\epsilon_s V_{bi}}{e} \left[\frac{N_a + N_d}{N_a N_d} \right] \right\}^{1/2}$$

Applying a reverse bias

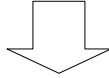
- Increase the barrier for electron injection from the n-type region into the p-type region and vice versa.
- Hardly any currents are flowing \Rightarrow electrostatic approximation, so:

$$V_{\text{total}} = V_{bi} + V_R$$

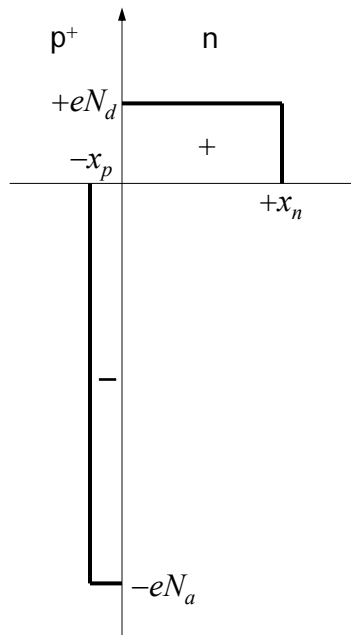
$$W = \left\{ \frac{2\epsilon_s (V_{bi} + V_R)}{e} \left[\frac{N_a + N_d}{N_a N_d} \right] \right\}^{1/2}$$



$$x_n = \sqrt{\frac{2\epsilon_s(V_{bi} + V_R)}{e} \left[\frac{N_a}{N_d} \right] \left[\frac{1}{N_a + N_d} \right]}; \quad C' = \frac{dQ'}{dV_R} = eN_d \frac{dx_n}{dV_R}$$

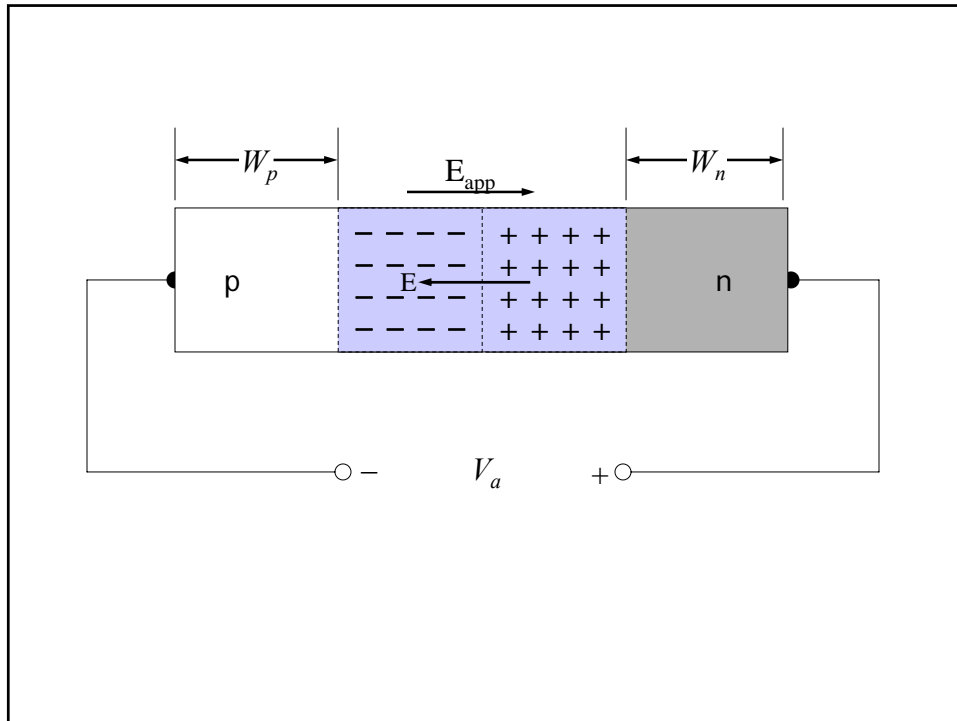


$$C' = \sqrt{\frac{e\epsilon_s N_a N_d}{2(V_{bi} + V_R)(N_a + N_d)}}; \quad C' = \frac{\epsilon_s}{W}$$



$$W \approx \sqrt{\frac{2\epsilon_s(V_{bi} + V_R)}{eN_d}}$$

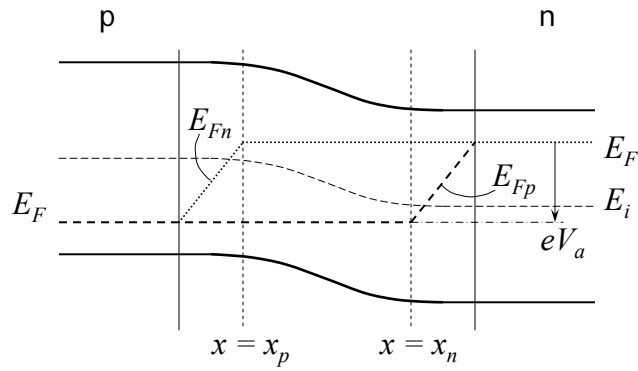
$$C' \approx \sqrt{\frac{e\epsilon_s N_d}{2(V_{bi} + V_R)}}$$



Assumptions for ideal J, V relation

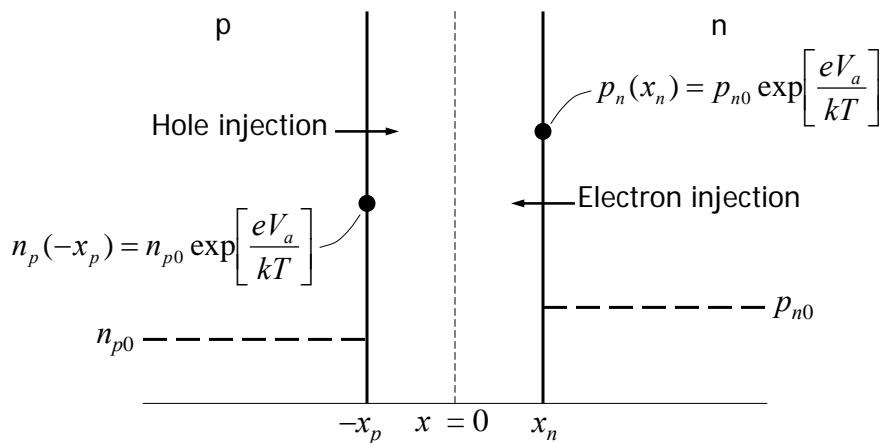
1. Abrupt boundaries between quasi-neutral region and depletion region.
2. Maxwell-Boltzmann approximation is valid.
3. Assume low-level injection.
4. In the structure:
 - The total current is constant
 - Individual electron and hole currents are continuous.
 - Individual electron and hole currents are constant in the depletion region.

Determination of the boundary conditions



$$p_n(x_n) = n_i \exp\left[\frac{E_i - E_{Fp}}{kT}\right] = n_i \exp\left[\frac{E_i - E_F}{kT}\right] \exp\left[\frac{eV_a}{kT}\right] = p_{n0} \exp\left[\frac{eV_a}{kT}\right]$$

$$n_p(x_p) = n_i \exp\left[\frac{E_{Fn} - E_i}{kT}\right] = n_i \exp\left[\frac{E_F - E_i}{kT}\right] \exp\left[\frac{eV_a}{kT}\right] = n_{p0} \exp\left[\frac{eV_a}{kT}\right]$$



Apply ambipolar transport equation:

$$D_p \frac{\partial^2(\delta p_n)}{\partial x^2} - \mu_p E \frac{\partial(\delta p_n)}{\partial x} + g' - \frac{\delta p_n}{\tau_{p0}} = \frac{\partial(\delta p_n)}{\partial t}$$

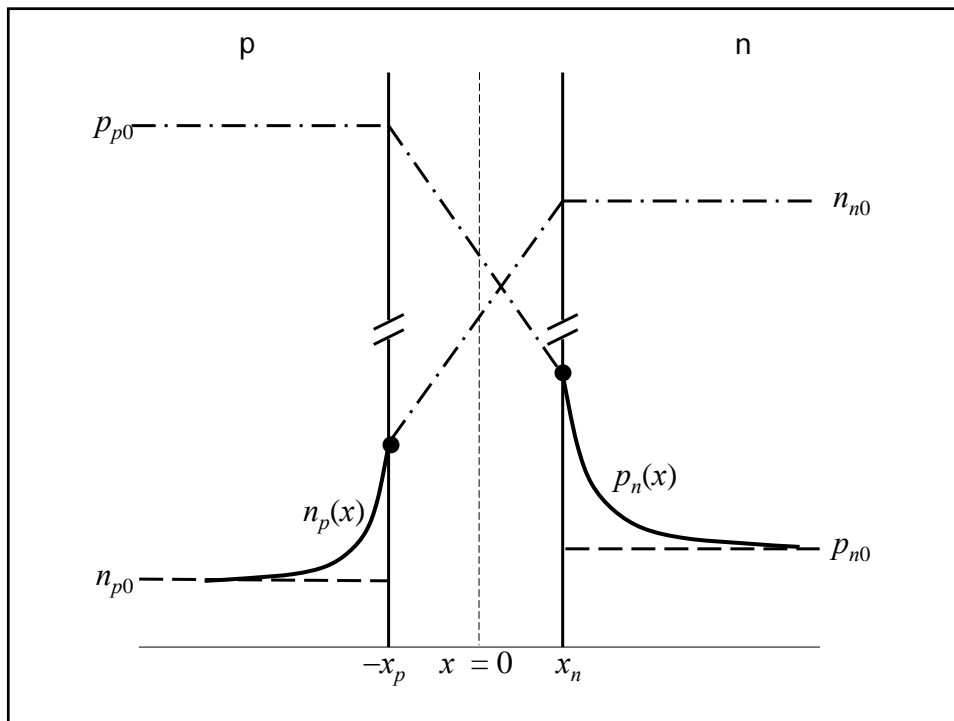
$$\Rightarrow \frac{d^2(\delta p_n)}{dx^2} - \frac{\delta p_n}{L_p^2} = 0 \quad (x > x_n)$$

Solve differential equation (try exponential function: $Ae^{-x/L} + Be^{x/L}$)

And apply the correct boundary conditions: $\delta p_n(x \rightarrow \infty) = 0$

$$\delta p_n(x) = p_n(x) - p_{n0} = p_{n0} \left[\exp\left(\frac{eV_a}{kT}\right) - 1 \right] \exp\left(\frac{x_n - x}{L_p}\right)$$

$$\delta n_p(x) = n_p(x) - n_{p0} = n_{p0} \left[\exp\left(\frac{eV_a}{kT}\right) - 1 \right] \exp\left(\frac{x_p + x}{L_n}\right)$$



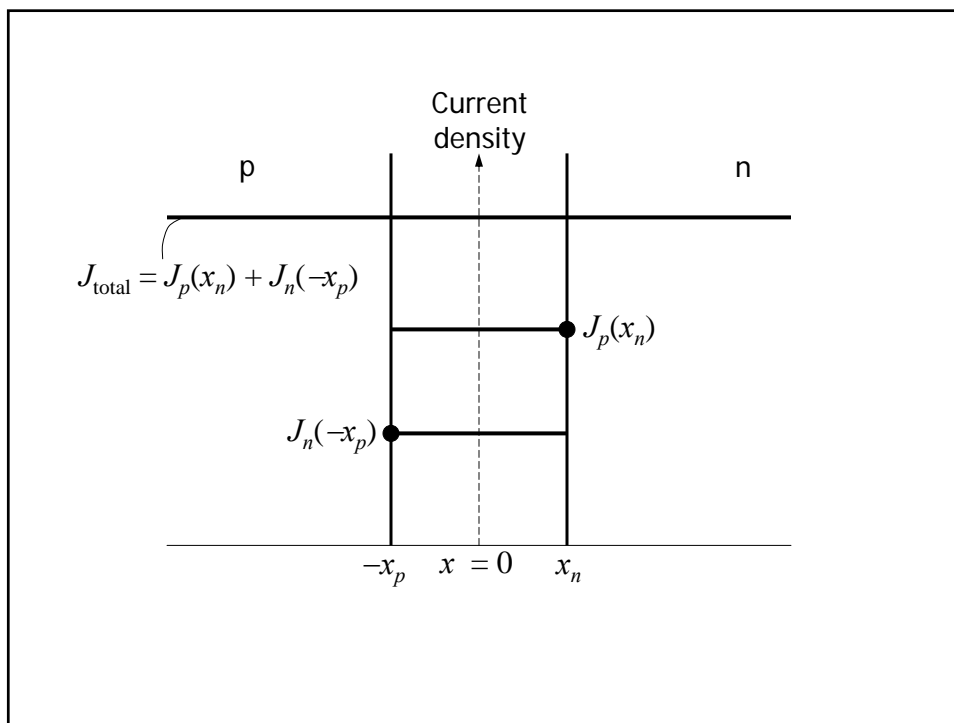
The current density through the junction

$$J_n(x_p) = eD_n \left. \frac{dn}{dx} \right|_{x=x_p} = eD_n \left. \frac{d(\delta n(x))}{dx} \right|_{x=x_p} = \frac{eD_n n_{p0}}{L_p} \left[\exp\left(\frac{eV_a}{kT}\right) - 1 \right]$$

$$J_p(x_n) = -eD_p \left. \frac{dp}{dx} \right|_{x=x_n} = -eD_p \left. \frac{d(\delta p(x))}{dx} \right|_{x=x_n} = \frac{eD_p p_{n0}}{L_n} \left[\exp\left(\frac{eV_a}{kT}\right) - 1 \right]$$

The total current is the addition of the electron and hole currents and is determined by the minority properties!!!

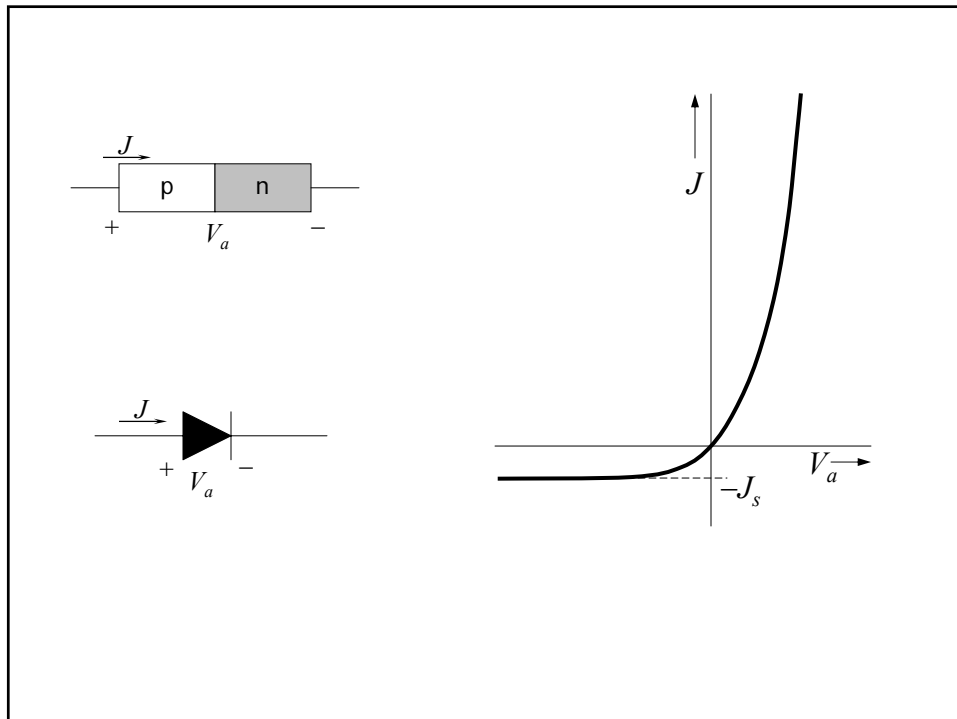
$$J = J_p(x_n) + J_n(x_p) = \left[\frac{eD_p p_{n0}}{L_p} + \frac{eD_n n_{p0}}{L_n} \right] \left[\exp\left(\frac{eV_a}{kT}\right) - 1 \right]$$



Diode equation

$$J = J_s \left[\exp\left(\frac{eV_a}{kT}\right) - 1 \right]$$

$$J_s = \left[\frac{eD_p p_{n0}}{L_p} + \frac{eD_n n_{p0}}{L_n} \right]$$



Generation-recombination current

Assumptions:

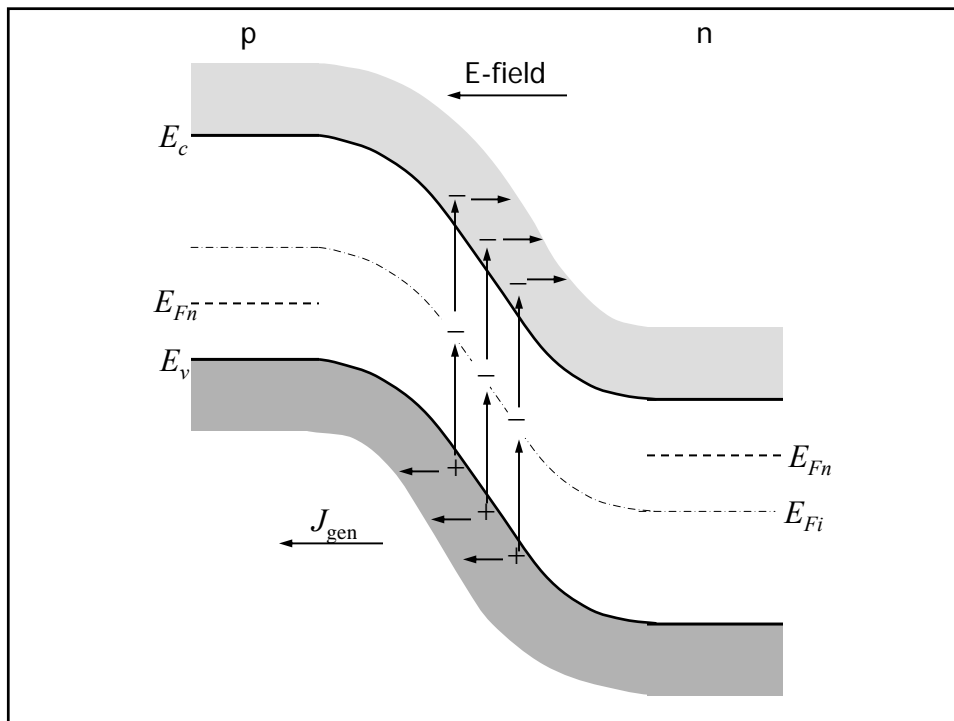
1. In the whole depletion region $n = p = 0$
2. Further: $\tau_0 = (\tau_{n0} + \tau_{p0})/2$, and use: $1/N_t C_{p,n} = t_{p0,n0}$
3. Trap energy level E_t in the middle of the gap $\rightarrow n' = p' = n_i$

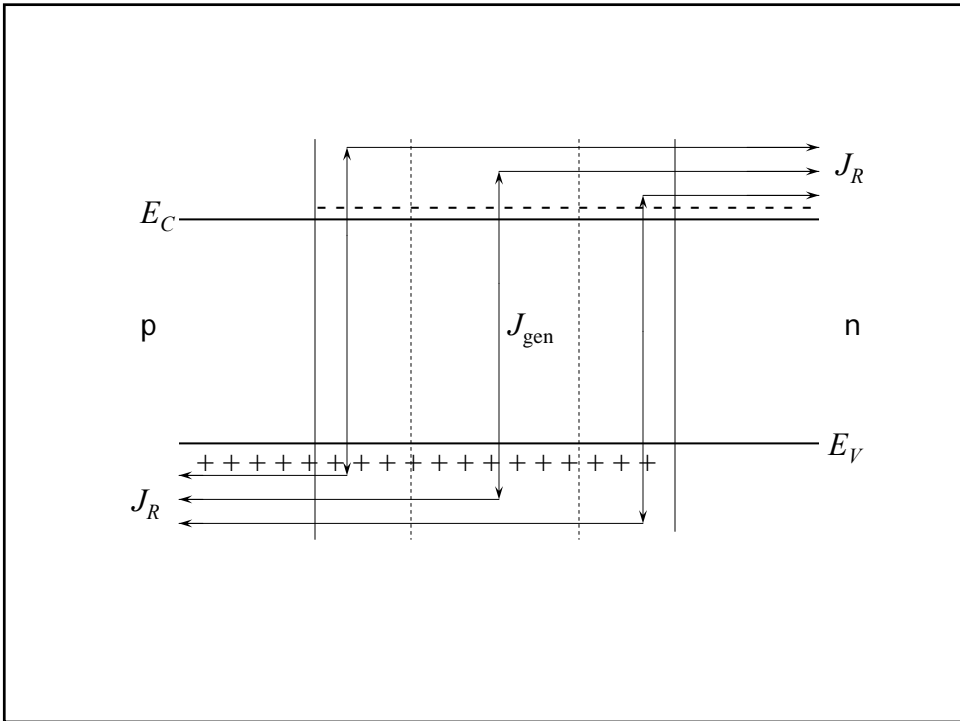
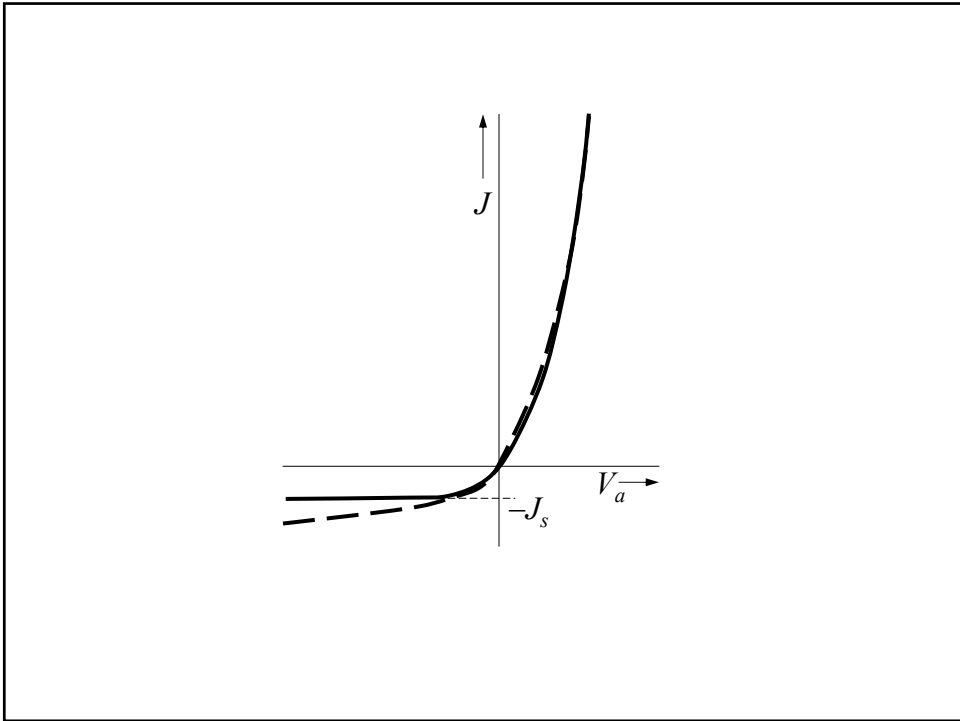
$$\text{So: } R = \frac{C_n C_p N_t (np - n_i^2)}{C_n (n + n') + C_p (p + p')} = \frac{-n_i}{2\tau_0} \equiv -G$$

The generation current is all the current generated in the depletion region, thus:

$$J_{\text{gen}} = \int_0^W eG dx = \frac{en_i W}{2\tau_0} \Rightarrow J_{\text{reverse}} = J_s + J_{\text{gen}}$$

Note that J_{reverse} is dependent on V_a because W and thus J_{gen} is dependent on V_a !!!

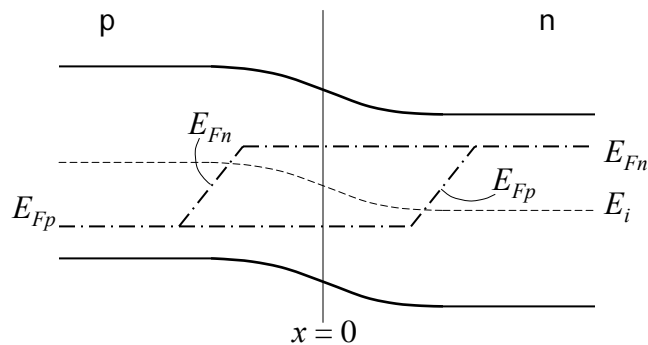




Forward recombination current

$$R = \frac{C_n C_p N_t (np - n_i^2)}{C_n (n + n') + C_p (p + p')} = \frac{np - n_i^2}{\tau_{p0} (n + n') + \tau_{n0} (p + p')}$$

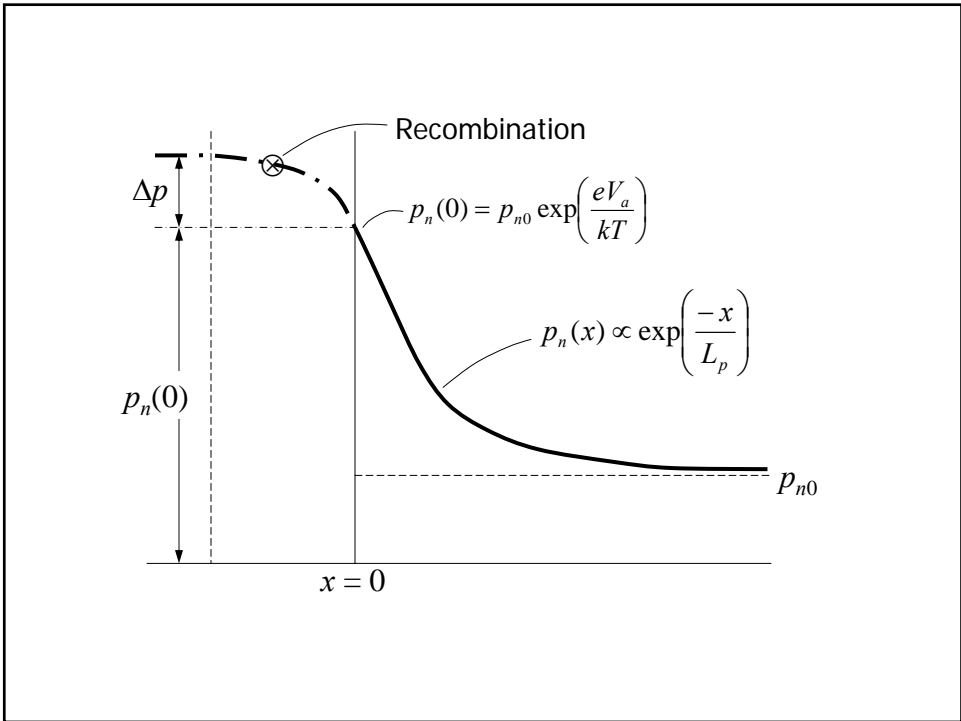
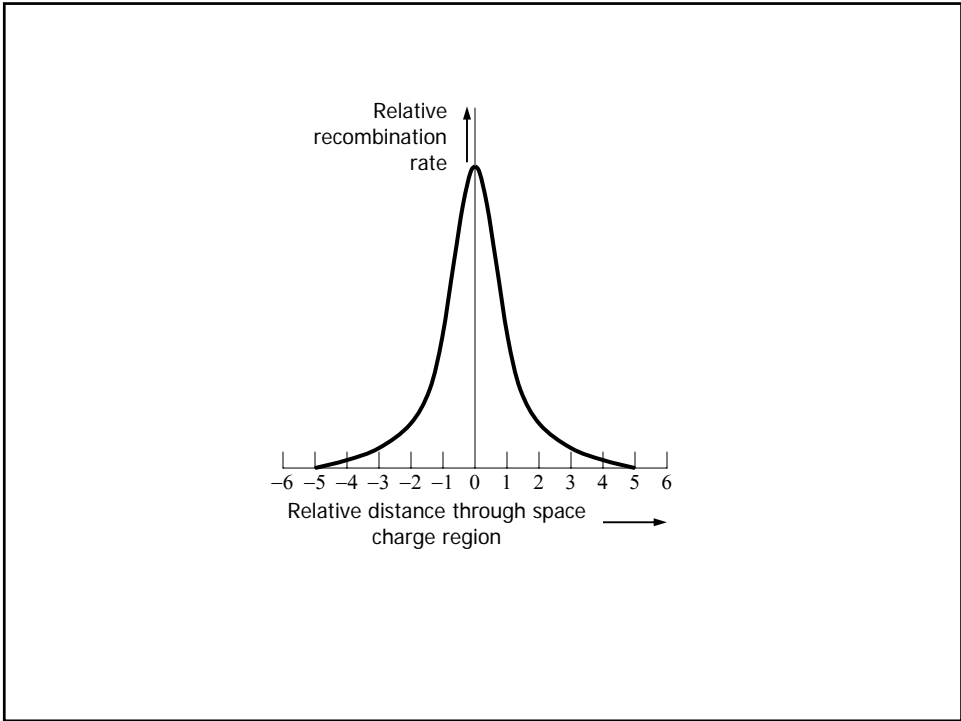
- Charge carriers injected in the depletion region under forward bias, can recombine in that region via states in the band gap.
- First determine where the recombination rate, R , is maximal.
- R is maximal when:
 1. The product np in the numerator is maximal and \rightarrow if $x = 0$
 2. The trap energy level E_t (that determines n' and p') is close to E_{fi} .



$$R = \frac{np - n_i^2}{\tau_{p0} (n + n') + \tau_{n0} (p + p')}$$

$$n = n_i \exp\left[\frac{E_{Fn} - E_{Fi}}{kT}\right]$$

$$p = n_i \exp\left[\frac{E_{Fi} - E_{Fp}}{kT}\right]$$



Forward recombination current

From the assumptions \rightarrow

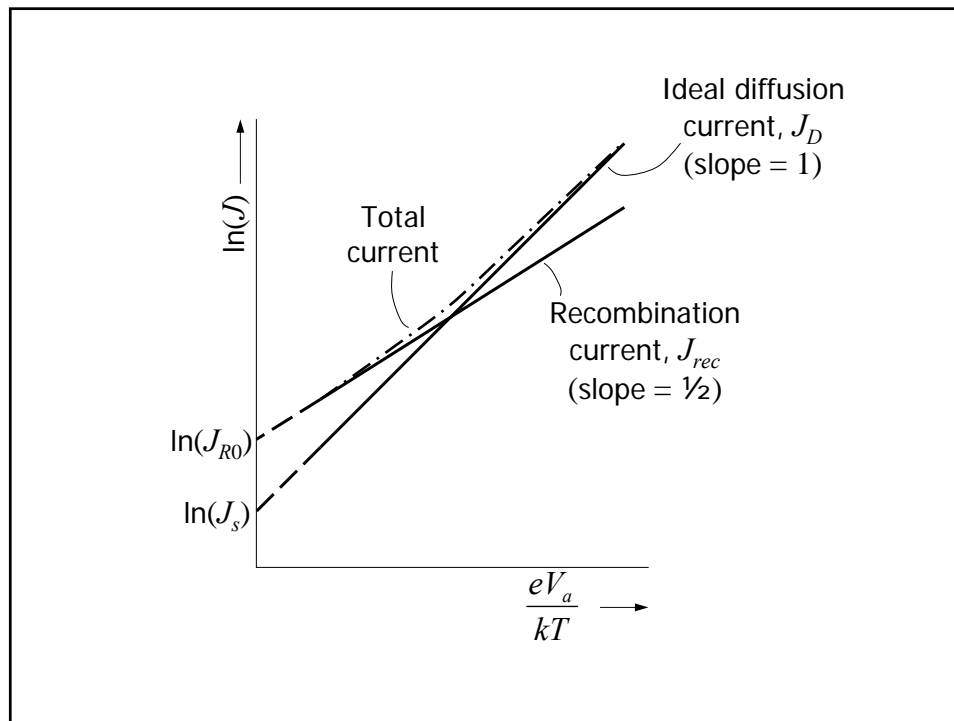
$$n = p = n_i \exp\left(\frac{eV_a}{2kT}\right)$$

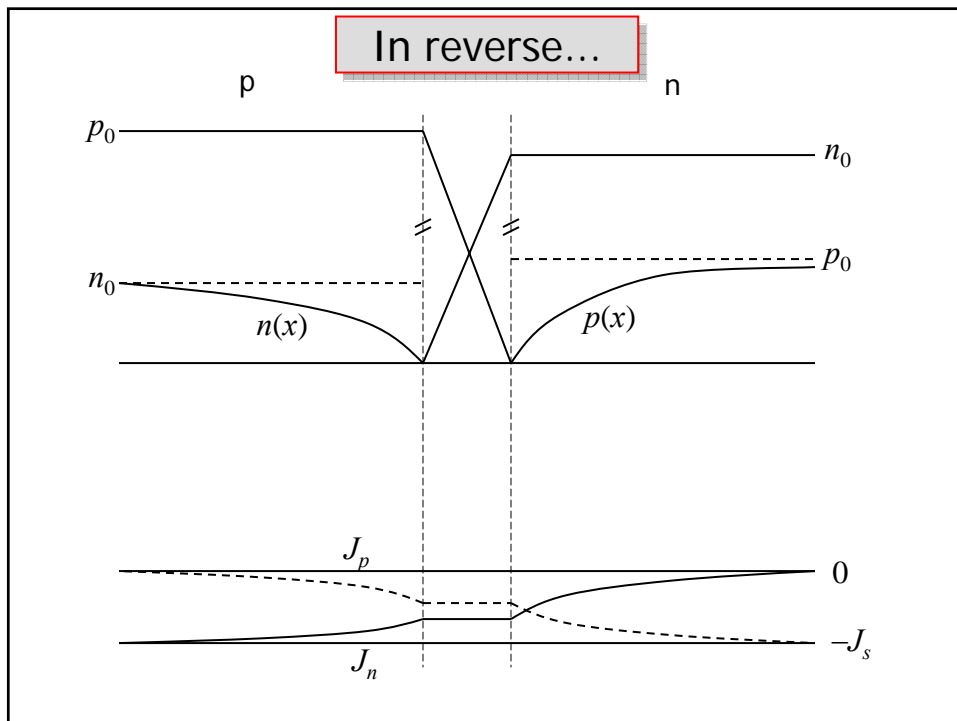
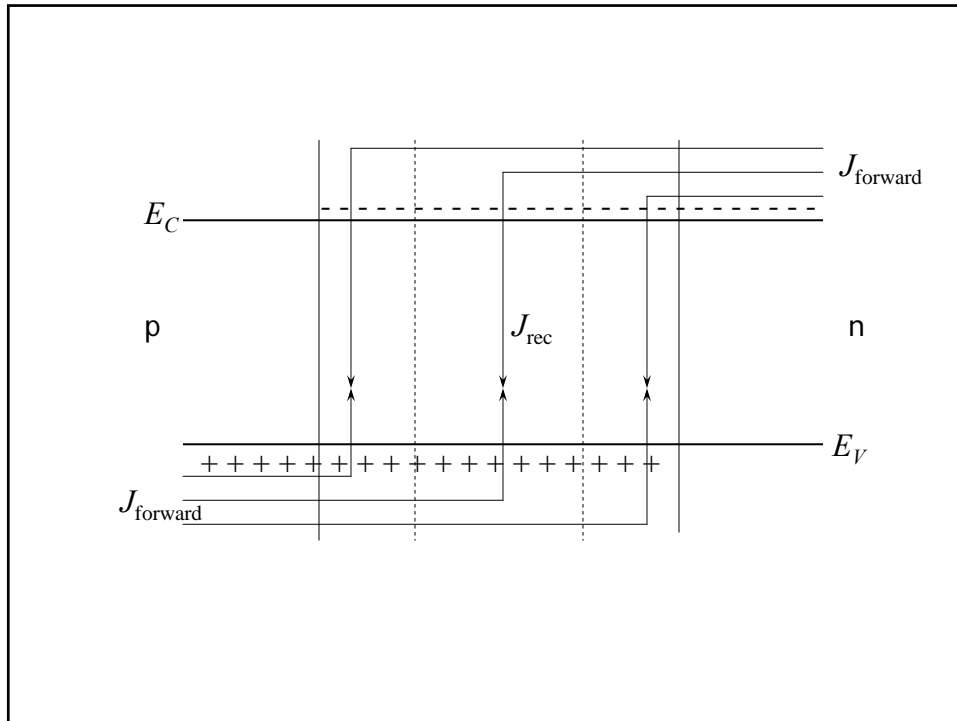
$$\left. \begin{aligned} n' &= n_i \exp\left(\frac{E_t - E_{Fi}}{kT}\right) \\ p' &= n_i \exp\left(\frac{E_{Fi} - E_t}{kT}\right) \end{aligned} \right\} \Rightarrow n' = p' = n_i$$

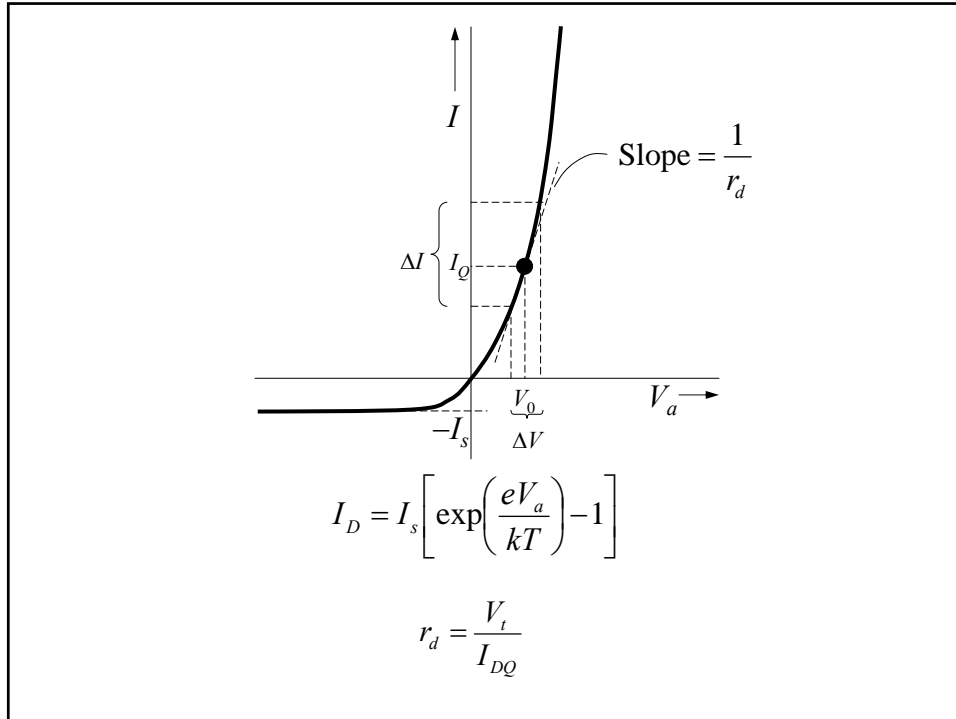
And thus the recombination and the current becomes \downarrow

$$R_{\max} = \frac{n_i}{2\tau_0} \frac{[\exp(eV_a/kT) - 1]}{[\exp(eV_a/2kT) + 1]} \approx \frac{n_i}{2\tau_0} \exp\left(\frac{eV_a}{2kT}\right)$$

$$J_{\text{rec}} = \int_0^W eR dx \approx \frac{eWn_i}{2\tau_0} \exp\left(\frac{eV_a}{2kT}\right) = J_{r0} \exp\left(\frac{eV_a}{2kT}\right)$$







Small-signal admittance

- In this case the *time* dependent transport equation for minority carriers should be applied: $E = 0$, $g' = 0$ and $\partial/\partial t \neq 0$.
- The bias across the depletion region is equal to the applied bias at any moment.
- The bias across the depletion region is in equilibrium with the minority carrier concentration on the depletion region edge at any moment.

Admittance

The admittance of the diode is:

$$Y = \frac{\hat{I}_p + \hat{I}_n}{\hat{V}_1} = \frac{1}{V_t} \left[I_{p0} \sqrt{1 + j\omega\tau_{p0}} + I_{n0} \sqrt{1 + j\omega\tau_{n0}} \right]$$

For small $\omega\tau_{p0} \ll 1$ and $\omega\tau_{n0} \ll 1$ we obtain the form $Y = g_d + j\omega C_d$, which in turn can be related to an equivalent circuit:

$$g_d = \frac{I_{p0} + I_{n0}}{V_t} \quad \leftarrow \text{diffusion conductance}$$

$$C_d = \frac{I_{p0}\tau_{p0} + I_{n0}\tau_{n0}}{2V_t} \quad \leftarrow \text{diffusion capacitance}$$

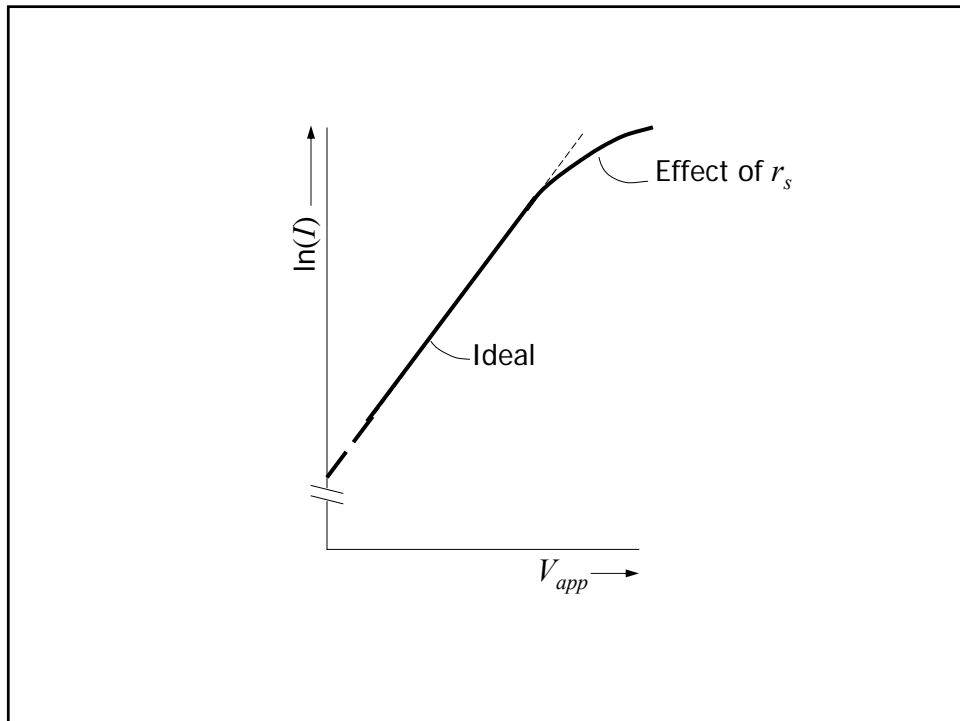
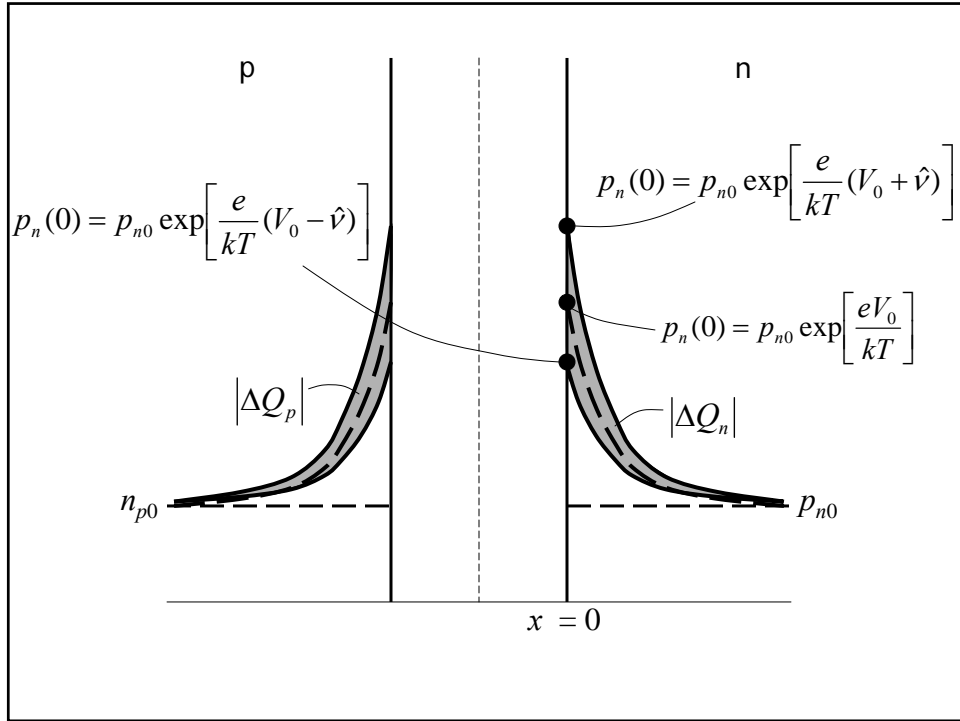
Diffusion capacitance

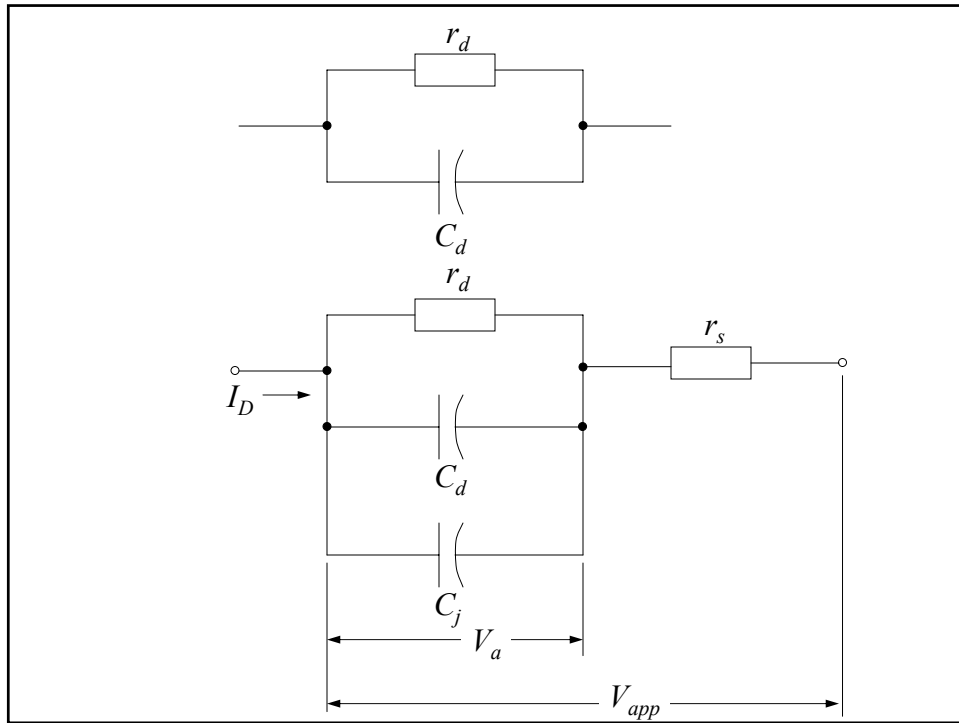
Minority carrier storage in n-region: $Q_p = e \int_{x_n}^{\infty} (p_n - p_{n0}) dx$

$$= e \int_{x_n}^{\infty} p_{n0} (e^{eV/kT} - 1) e^{-(x-x_n)/L_p} dx$$

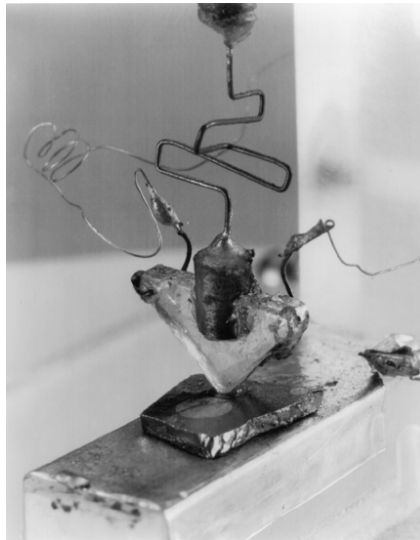
$$= eL_p p_{n0} (e^{eV/kT} - 1)$$

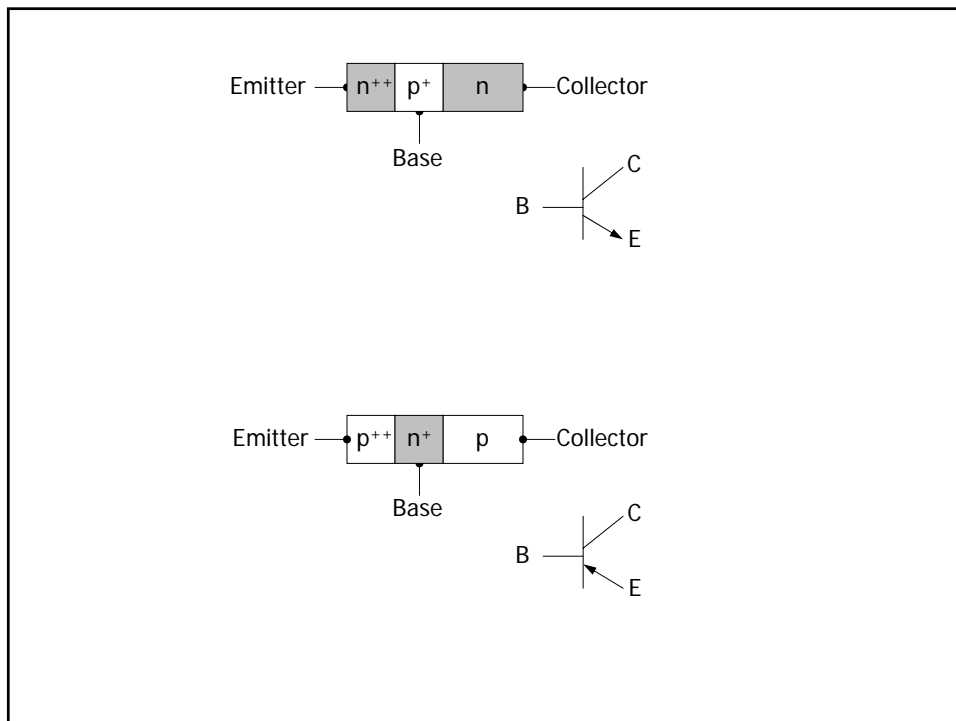
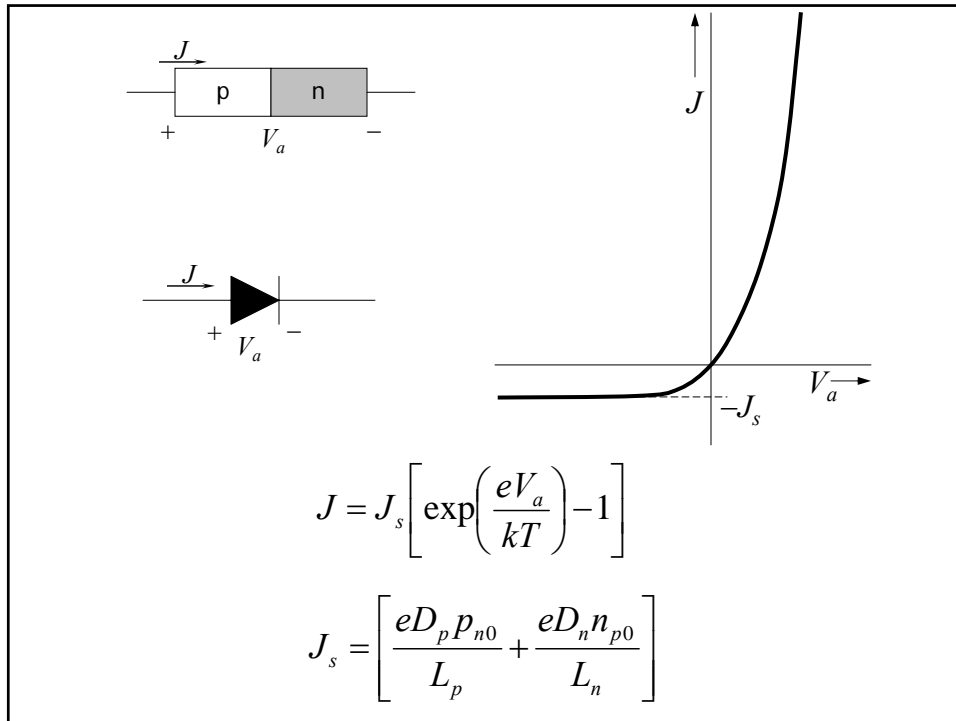
Diffusion capacitance becomes: $C_d = \frac{dQ_p}{dV} = e \cdot \left(\frac{1}{V_t} \right) \cdot L_p p_{n0} e^{eV/kT}$

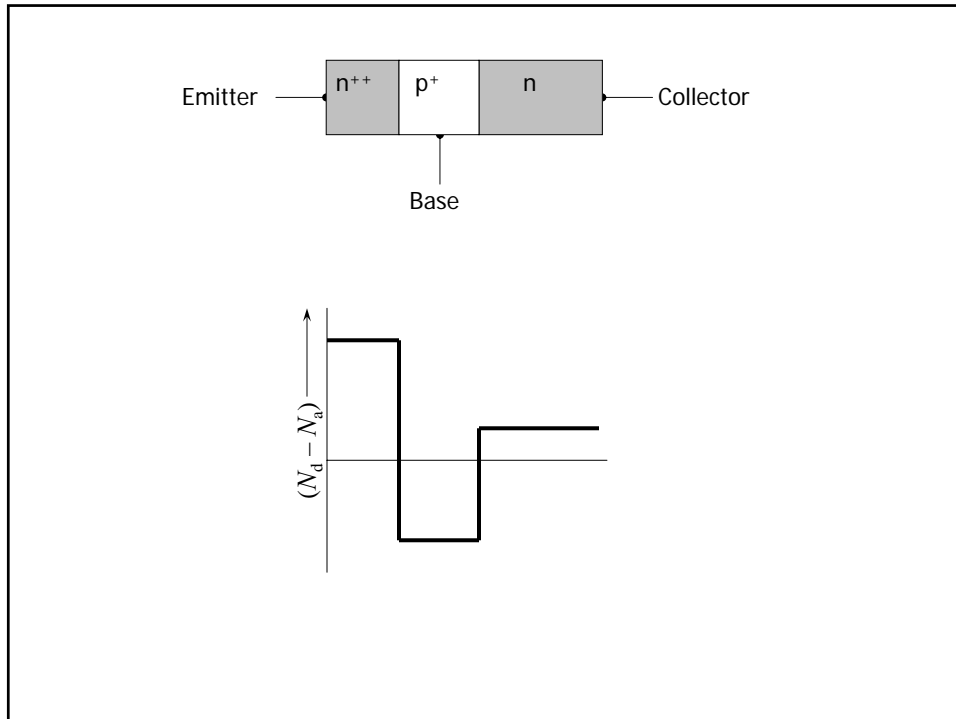




The transfer resistor...







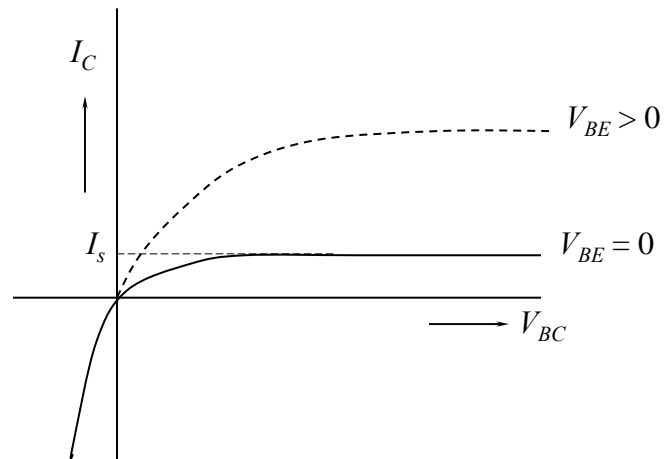
Characteristics in forward-active mode

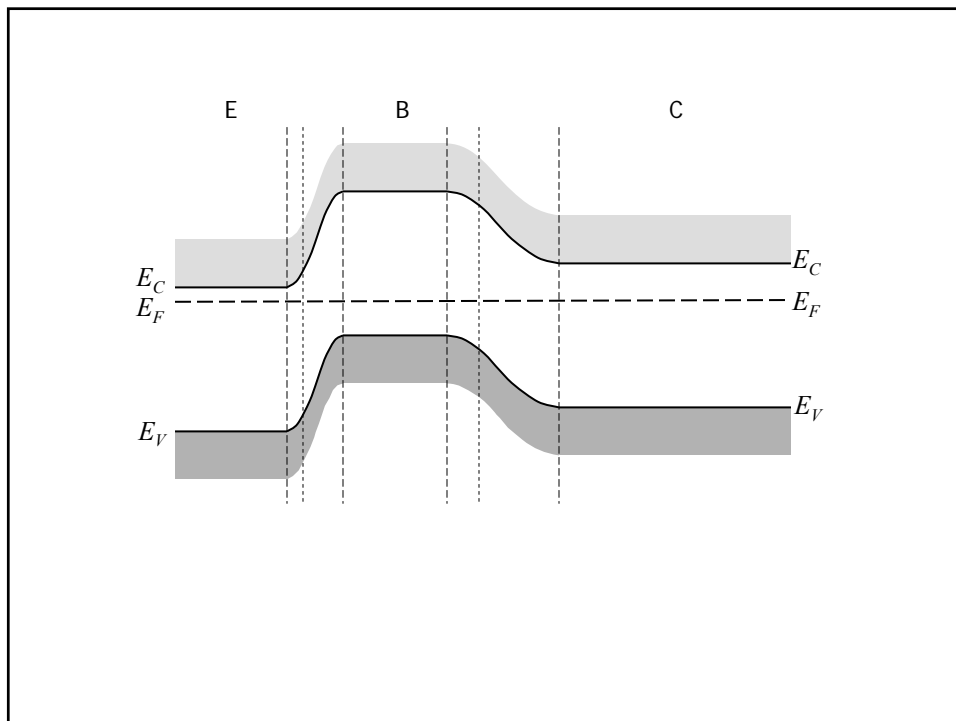
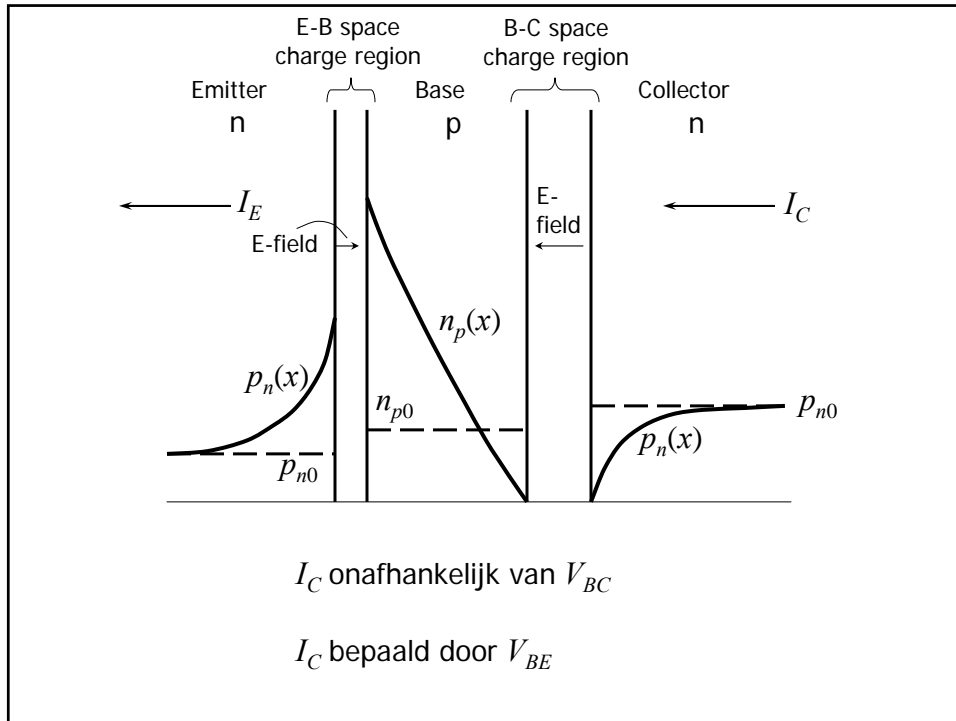
- Short base width, so the emitter-base junction is in principle a short diode
- Emitter-base junction is forward biased, the base-collector junction is reversed biased
- In an n-p-n transistor electrons are injected from the emitter into the base
- The electron concentration near the depletion region of the base-collector junction is zero → large electron-concentration gradient

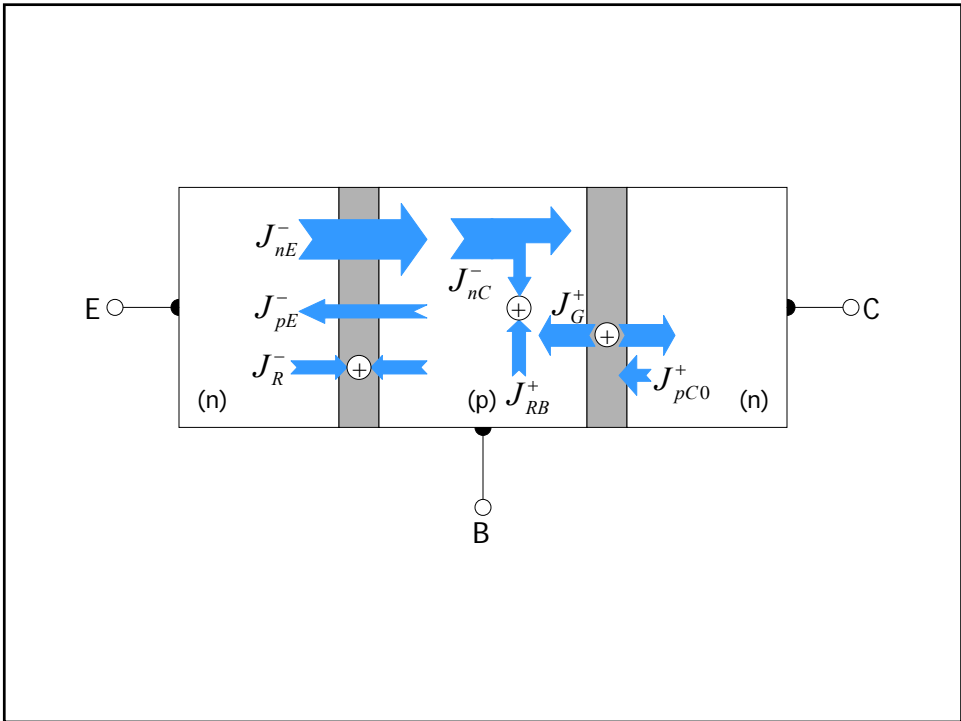
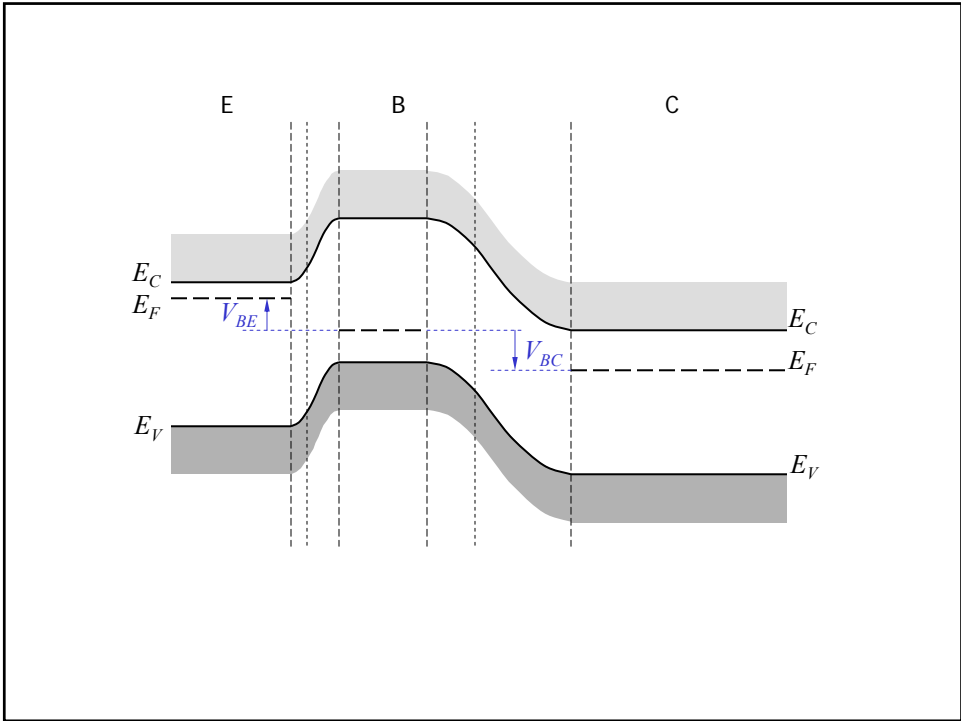
Characteristics in forward-active mode

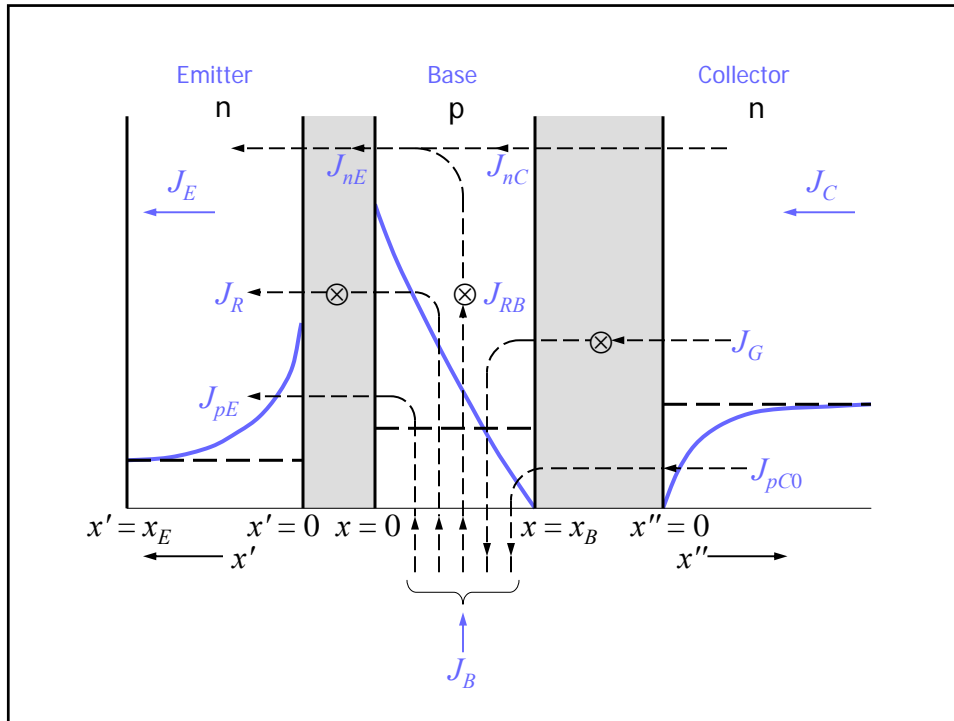
- Ideally, all electrons injected into base reach collector → collector current independent of base-collector bias and determined by the emitter-base bias

⇒ Transistor action









Current components of the transistor and current gain factor

$$J_C = J_{nC} + J_G + J_{pC0}$$

$$J_E = J_{nE} + J_R + J_{pE}$$

$$J_B = -J_E - J_C$$

The dc common base current gain factor is defined as: $\alpha_0 = \frac{I_C}{I_E}$

If we assume that the emitter-base area is equal to the base-collector area, we obtain:

$$\alpha_0 = \frac{J_C}{J_E} = \frac{J_{nC} + J_G + J_{pC0}}{J_{nE} + J_R + J_{pE}}$$

Small-signal common base current gain

We are interested in the collector current-change as a function of the emitter-current change:

$$\alpha = \left. \frac{\partial J_C}{\partial J_E} \right|_{V_{BC}} = \frac{J_{nC}}{J_{nE} + J_R + J_{pE}}$$

$$= \underbrace{\left(\frac{J_{nE}}{J_{nE} + J_{pE}} \right)}_{\gamma} \underbrace{\left(\frac{J_{nC}}{J_{nE}} \right)}_{\alpha_T} \underbrace{\left(\frac{J_{nE} + J_{pE}}{J_{nE} + J_R + J_{pE}} \right)}_{\delta}$$

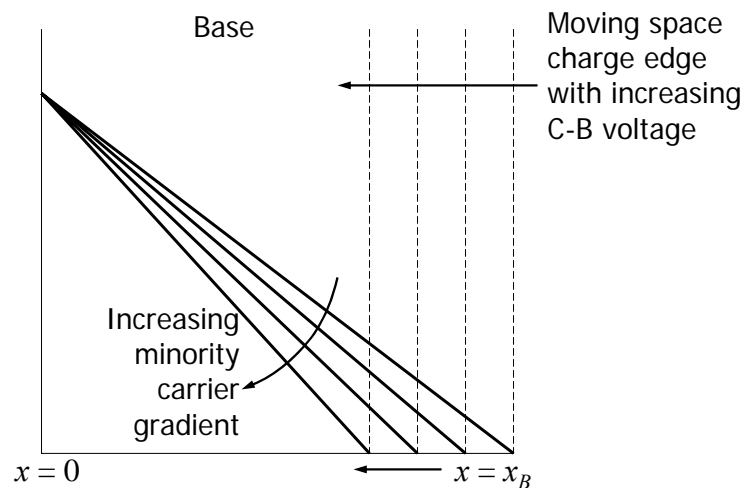
$$\alpha = \underbrace{\left(\frac{J_{nE}}{J_{nE} + J_{pE}} \right)}_{\gamma} \underbrace{\left(\frac{J_{nC}}{J_{nE}} \right)}_{\alpha_T} \underbrace{\left(\frac{J_{nE} + J_{pE}}{J_{nE} + J_R + J_{pE}} \right)}_{\delta}$$

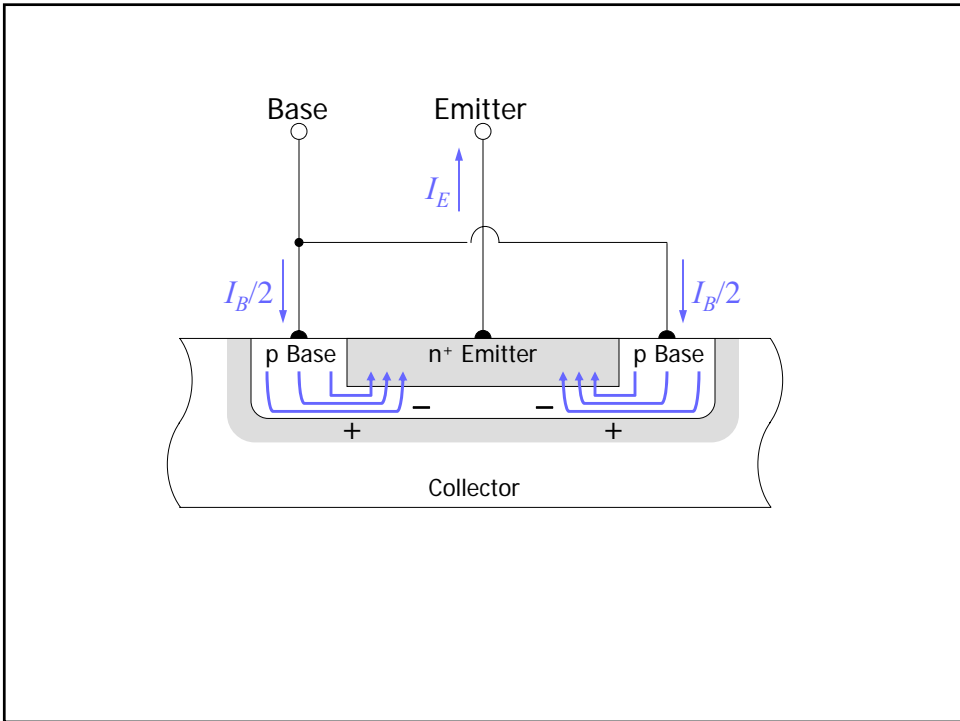
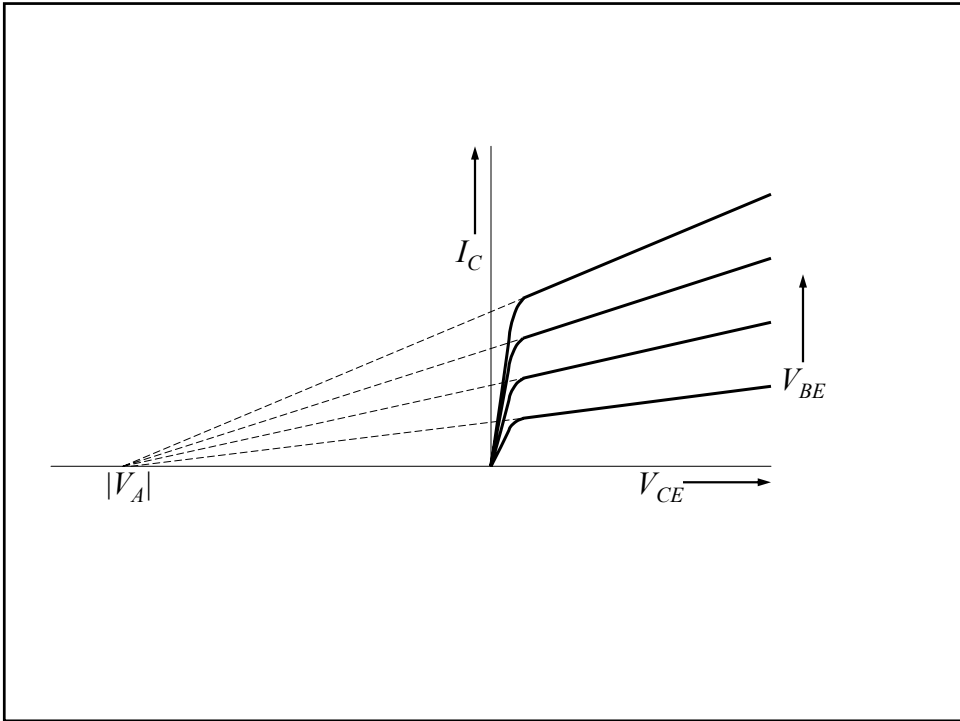
- Emitter efficiency injection factor, γ : ratio electron diffusion current / total diffusion current
- Base transport factor, α_T : determines the efficiency of charge transport across the base, in other words is a measure for the recombination losses in the base
- Recombination factor, δ : measure for the quality of the emitter-base junction and gives an indication about the recombination

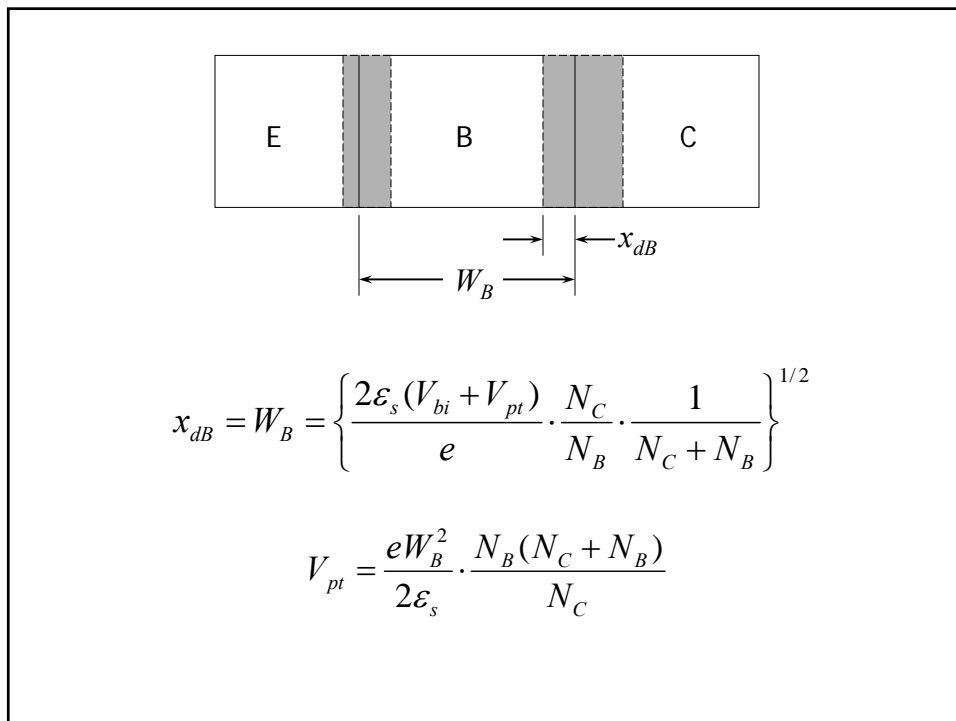
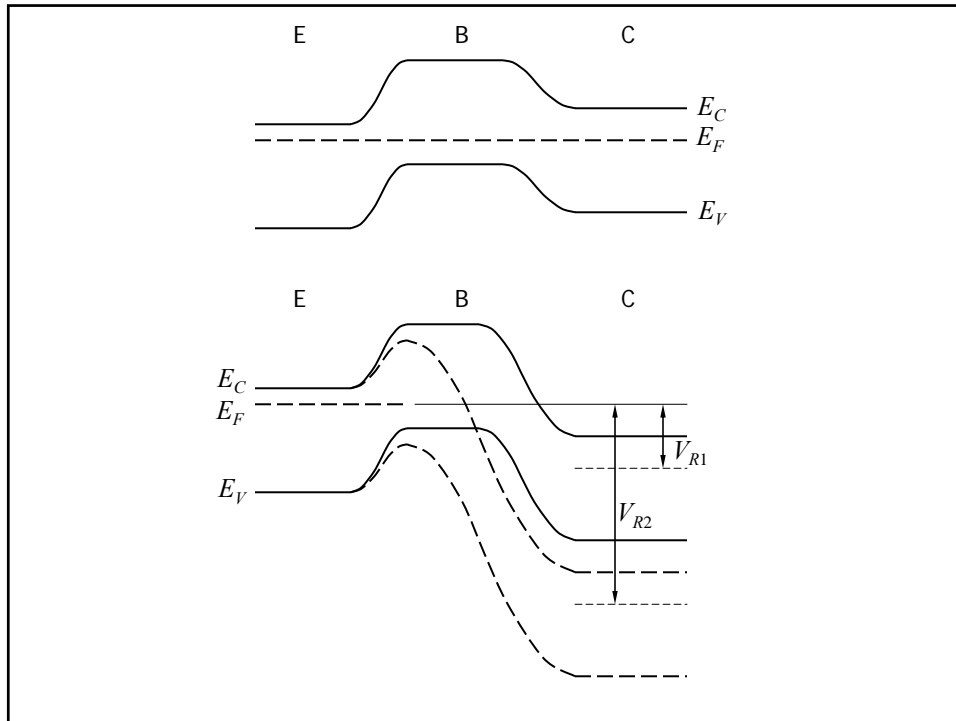
Non-ideal effects

So far we assumed that:

- All regions are uniformly doped,
- Low-level injection is valid,
- The emitter- and base widths are constant,
- The band gap is constant in the whole device,
- The current densities are uniform and
- There is no breakdown

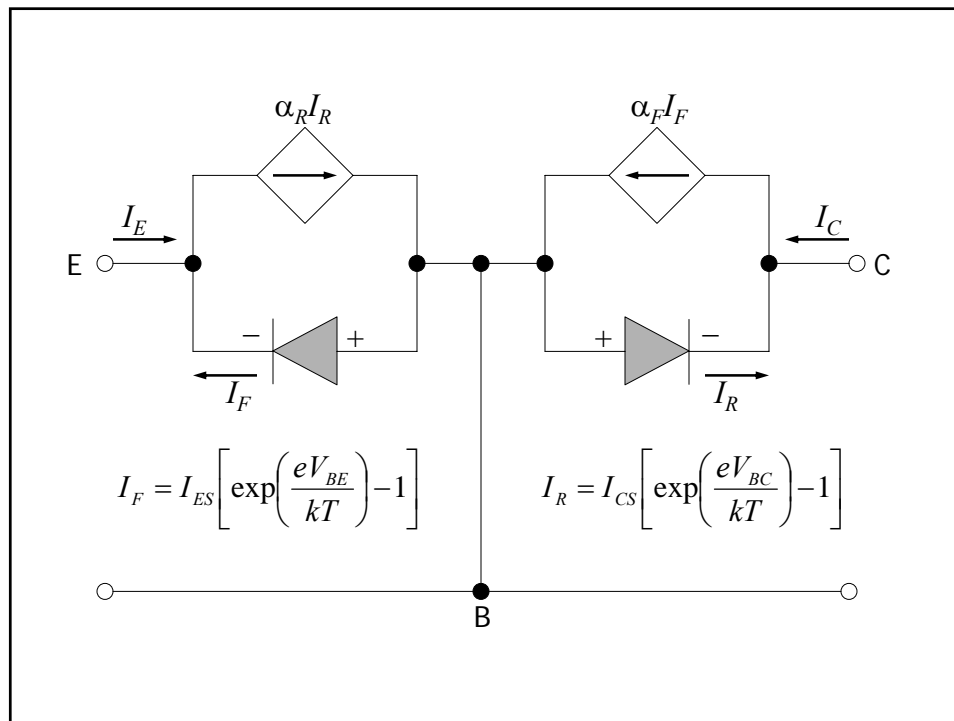






Ebers-Moll model

- Transistor represented by two interacting diodes with common base
- Forward current of one diode flows into the other reverse-biased diode. The emitter-base current is represented by I_F
- This current is a function of the emitter-base bias, V_{BE}
- In forward active mode a large part of the current injected into the base reaches the collector
- This fraction is represented by a current source with value $\alpha_F I_F$ in which α_F is the common-base current gain
- In the inverse mode the base-collector junction is forward biased and conducts a current I_R which is a function of the base-collector bias, V_{BC}
- Current across the base is now represented by a current source with value $\alpha_R I_R$



Ebers-Moll equations

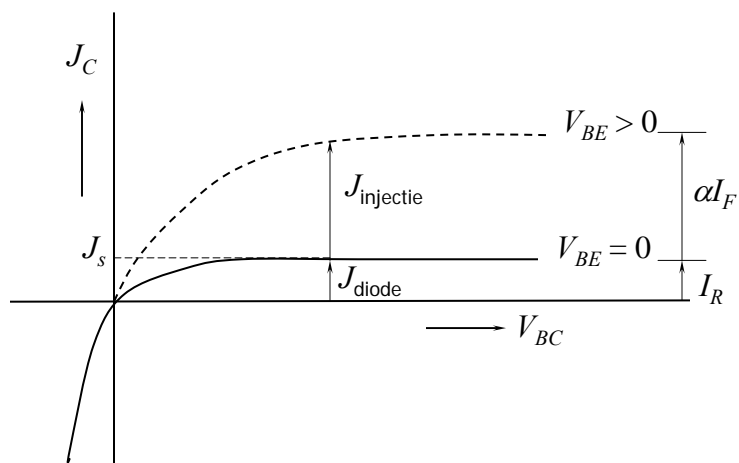
The Ebers-Moll equations follow from the equivalent circuit:

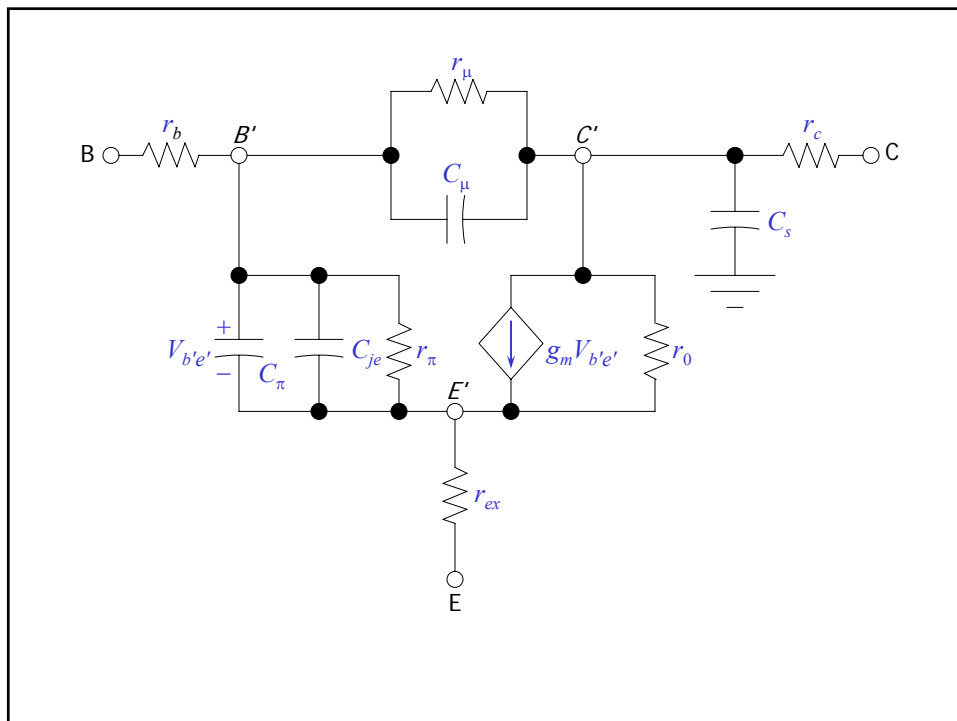
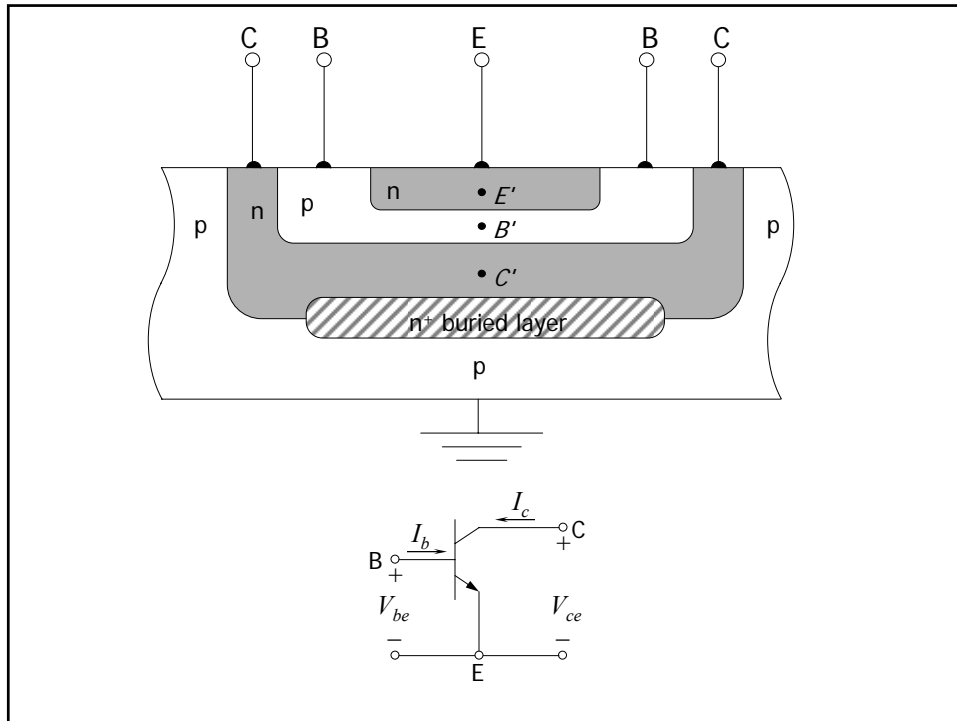
$$I_C = \alpha_F I_{ES} \left[\exp\left(\frac{eV_{BE}}{kT}\right) - 1 \right] - I_{CS} \left[\exp\left(\frac{eV_{BC}}{kT}\right) - 1 \right]$$

$$I_E = \alpha_R I_{CS} \left[\exp\left(\frac{eV_{BC}}{kT}\right) - 1 \right] - I_{ES} \left[\exp\left(\frac{eV_{BE}}{kT}\right) - 1 \right]$$

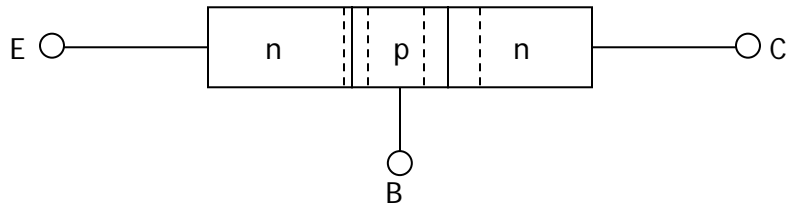
With I_{ES} and I_{CS} the reverse-bias currents of the emitter-base and the base-collector junction, respectively

$(J_C - V_{CB})_{V_{be}}$ characteristics





Cut-off frequency



$$\Delta I_E \xrightarrow{\tau_{ec}} \Delta V_{BC}$$

Time required to travel from the emitter to the collector:

$$\tau_{ec} = \tau_e + \tau_b + \tau_d + \tau_c$$

Charging time, τ_e , of the emitter-base junction capacitance:

$$\tau_e = r_e'(C_{je} + C_p) = \frac{kT}{e} \frac{1}{I_E} (C_{je} + C_p) \leftarrow \text{Emitter-base junction capacitance charging time}$$

Time required to diffuse across the base:

$$\begin{aligned} \tau_b &= \int_0^{\tau_b} dt = \int_0^{x_B} \frac{dx}{v(x)} = \int_0^{x_B} \frac{en_B(x)dx}{(-J_n)} \\ &= \frac{x_B^2}{2D_n} \leftarrow \text{Base transit time} \end{aligned}$$

Time required to cross the depletion region between the base and the collector:

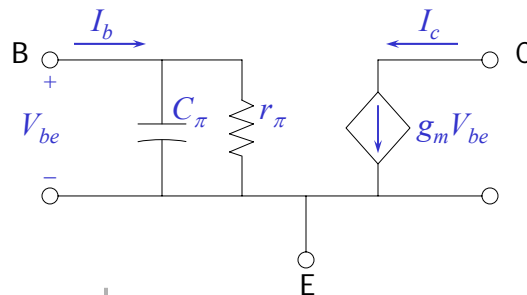
$$\tau_d = \frac{x_{dc}}{v_s} \leftarrow \begin{array}{|l|} \hline \text{Collector depletion region} \\ \text{transit time} \\ \hline \end{array}$$

with: x_{dc} the base-collector depletion-region width and v_s the saturation velocity at high electric fields

Charging time, τ_c , of the base-collector junction capacitance:

$$\tau_c = r_c (C_\mu + C_s) \leftarrow \begin{array}{|l|} \hline \text{Collector capacitance} \\ \text{Charging time} \\ \hline \end{array}$$

with: C_μ the base-collector junction capacitance and C_s the collector-base capacitance



DC:

$$\begin{aligned} V_{be} &= I_b r_\pi \\ I_c &= g_m V_{be} = g_m r_\pi I_b \\ \frac{I_c}{I_b} &= g_m r_\pi \quad (= \beta_0) \end{aligned}$$

AC:

$$\begin{aligned} V_{be} &= I_b \frac{r_\pi}{1 + j\omega r_\pi C_\pi} \\ I_c &= g_m V_{be} = I_b \frac{g_m r_\pi}{1 + j\omega r_\pi C_\pi} \\ \frac{I_c}{I_b} &= \frac{g_m r_\pi}{1 + j\omega r_\pi C_\pi} = \frac{\beta_0}{1 + j(f/f_\beta)}, \text{ with } f_\beta = \frac{1}{2\pi r_\pi C_\pi} \end{aligned}$$

Definition cut-off frequency

$$f_\alpha \equiv \alpha \rightarrow \frac{\alpha_0}{\sqrt{2}}$$

$$f_\beta \equiv \beta \rightarrow \frac{\beta_0}{\sqrt{2}}$$

$$f_T \equiv \beta \rightarrow 1$$

$$\alpha = \frac{\alpha_0}{1 + j \frac{f}{f_\alpha}}$$

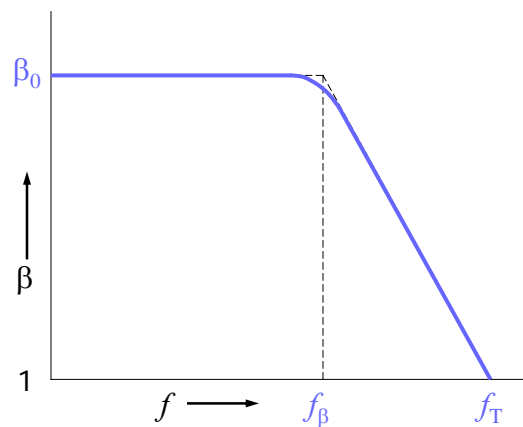
$$f_\alpha = \frac{1}{2\pi\tau_{ec}}$$

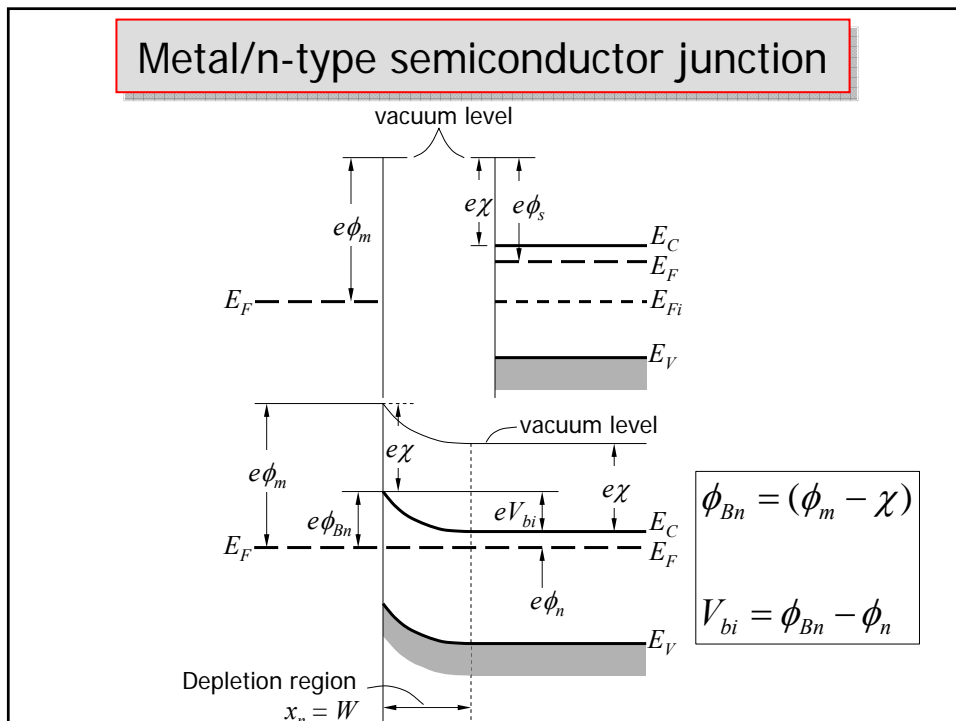
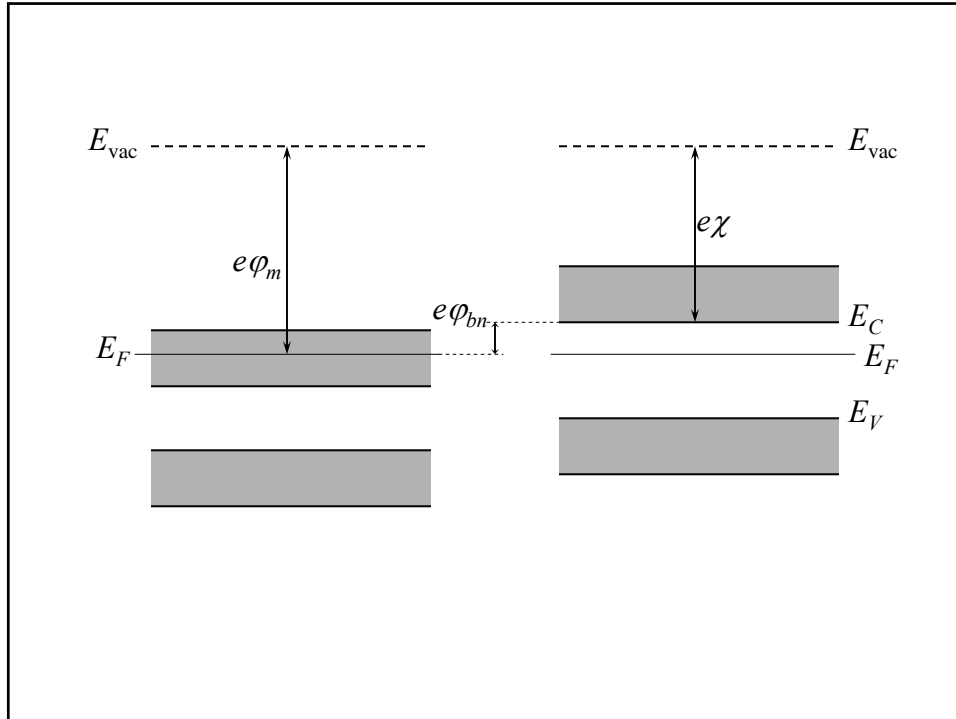
$$\beta = \frac{\alpha}{1 - \alpha} = \frac{\alpha_0}{1 - \alpha_0 + j \frac{f}{f_\alpha}}$$

$$|\beta| = \left| \frac{\alpha}{1 - \alpha} \right| \cong \frac{f_\alpha}{f}$$

Definition f_T : $|\beta| = 1$ if $f = f_T$

thus: $f_T = f_\alpha = \frac{1}{2\pi\tau_{ec}} \cong \beta_0 f_\beta$





Ideal junction characteristics

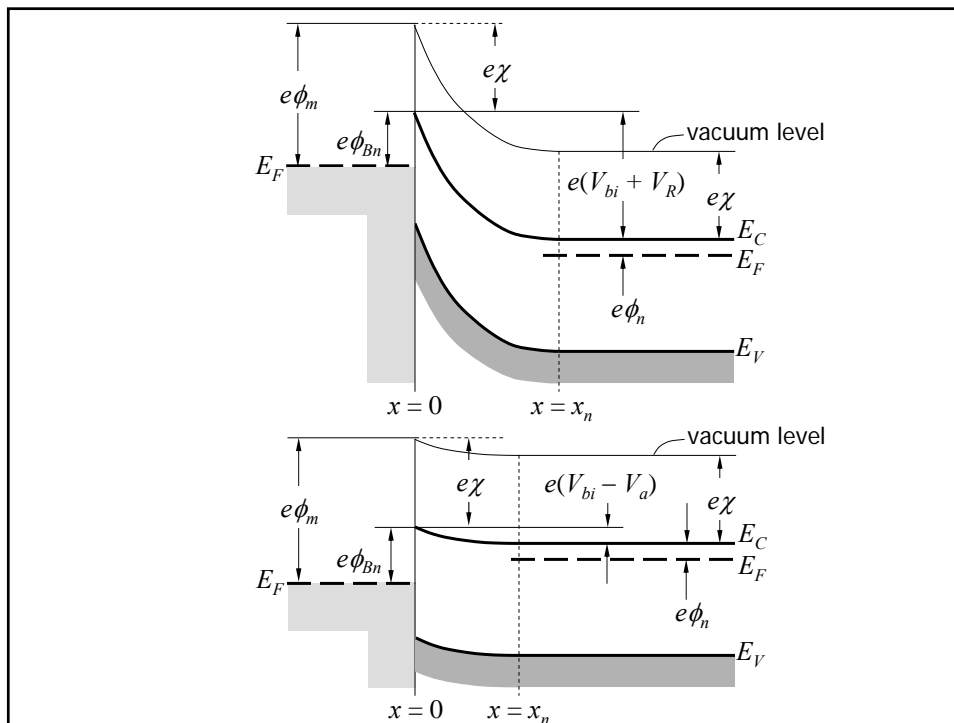
Poisson equation: $\frac{dE}{dx} = \frac{\rho(x)}{\epsilon_s}$

Then follows simply: $W = x_n = \left[\frac{2\epsilon_s(V_{bi} + V_R)}{eN_d} \right]^{1/2}$

$$C' = eN_d \frac{dx_n}{dV_R} = \left[\frac{e\epsilon_s N_d}{2(V_{bi} + V_R)} \right]^{1/2} \Rightarrow \left(\frac{1}{C'} \right)^2 \propto V_R$$

⇒ from C' measurement V_{bi} as N_d can be determined

⇒ subsequently ϕ_n and thus ϕ_{bn} can be calculated



Current-voltage relation

$$J = J_{sT} \left[\exp\left(\frac{eV_a}{kT}\right) - 1 \right]$$

$$J_{sT} = A^* T^2 \exp\left(-\frac{e\phi_{Bn}}{kT}\right), \quad \text{with: } A^* \equiv \frac{4\pi m_n^* k^2}{h^3}$$

Compare with p-n diode, in which:

$$J_s = \frac{eD_n n_{p0}}{L_n} + \frac{eD_p p_{n0}}{L_p}$$

Differences between Schottky and p-n diodes

- In a Schottky diode the current is determined by the majority carriers, in a p-n diode by the minority carriers.
- In a Schottky diode charge transport is determined by thermionic emission of majority carriers over a potential barrier, in a p-n diode by the diffusion of minority carriers.
- The saturation current of a Schottky diode is much larger than that of a p-n diode.
- A forward biased Schottky diode does not have diffusion capacitance → much faster device.

